

# CMS Phase-II Upgrade

Xiaohu SUN  
on behalf of CMS-China  
2022.11.27



# Why upgrade the CMS detector?

The challenging HL-LHC data-taking

It is all about the instantaneous luminosity!

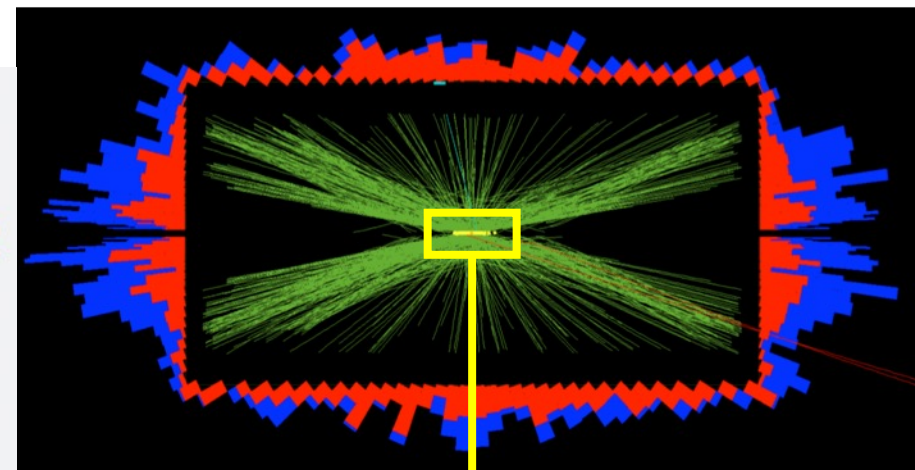
**LHC**

$2 \times 10^{34} \text{ s}^{-1} \text{ cm}^{-2}$   
 $O(10^{14} \text{ neq/cm}^2)$   
 $O(40)$



**HL-LHC**

up to  $7.5 \times 10^{34} \text{ s}^{-1} \text{ cm}^{-2}$   
 $>O(10^{15} \text{ neq/cm}^2)$   
 140-200



HL-LHC brings up to ~200 vertices per collision



~10 cm

# The Phase-II upgrade projects

## L1-Trigger HLT/DAQ

<https://cds.cern.ch/record/2714892>

<https://cds.cern.ch/record/2759072>

- Tracks in L1-Trigger at 40 MHz
- PFlow selection 750 kHz L1 output
- HLT output 7.5 kHz
- 40 MHz data scouting

## Calorimeter Endcap

<https://cds.cern.ch/record/2293646>

- 3D showers and precise timing, **HGCAL**
- Si, Scint+SiPM in Pb/W-SS

## Tracker

<https://cds.cern.ch/record/2272264>

- Si-Strip and Pixels increased granularity
- Design for tracking in L1-Trigger
- Extended coverage to  $\eta \approx 3.8$

## Barrel Calorimeters

<https://cds.cern.ch/record/2283187>

- ECAL crystal granularity readout at 40 MHz
- with precise timing for e/ $\gamma$  at 30 GeV
- ECAL and HCAL new Back-End boards

## Muon systems

<https://cds.cern.ch/record/2283189>

- DT & CSC new FE/BE readout
- RPC **Link**-board
- New **GEM/iRPC**  $1.6 < \eta < 2.4$
- Extended coverage to  $\eta \approx 3$

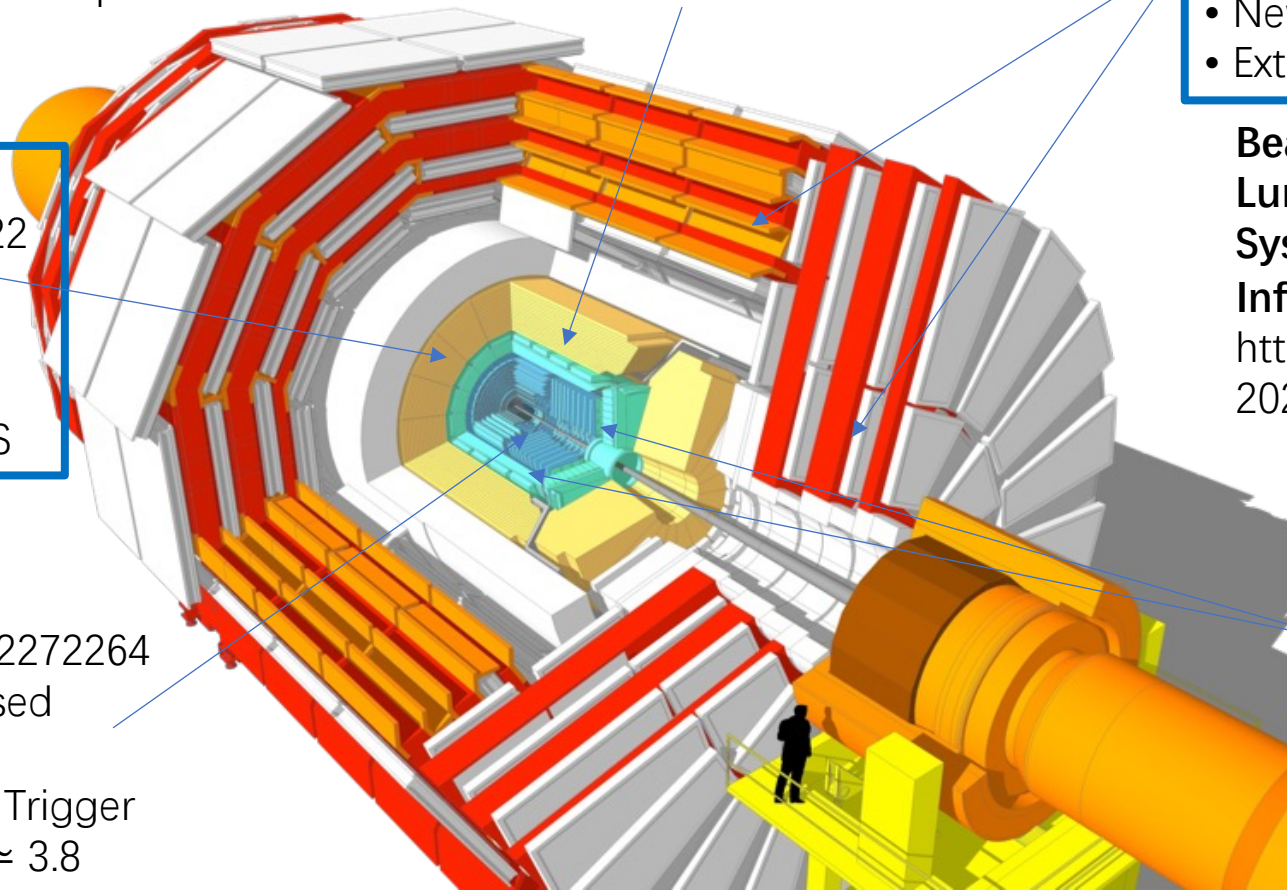
## Beam Radiation Instr. and Luminosity, and Common Systems and Infrastructure

<https://cds.cern.ch/record/2020886>

## MIP Timing Detector

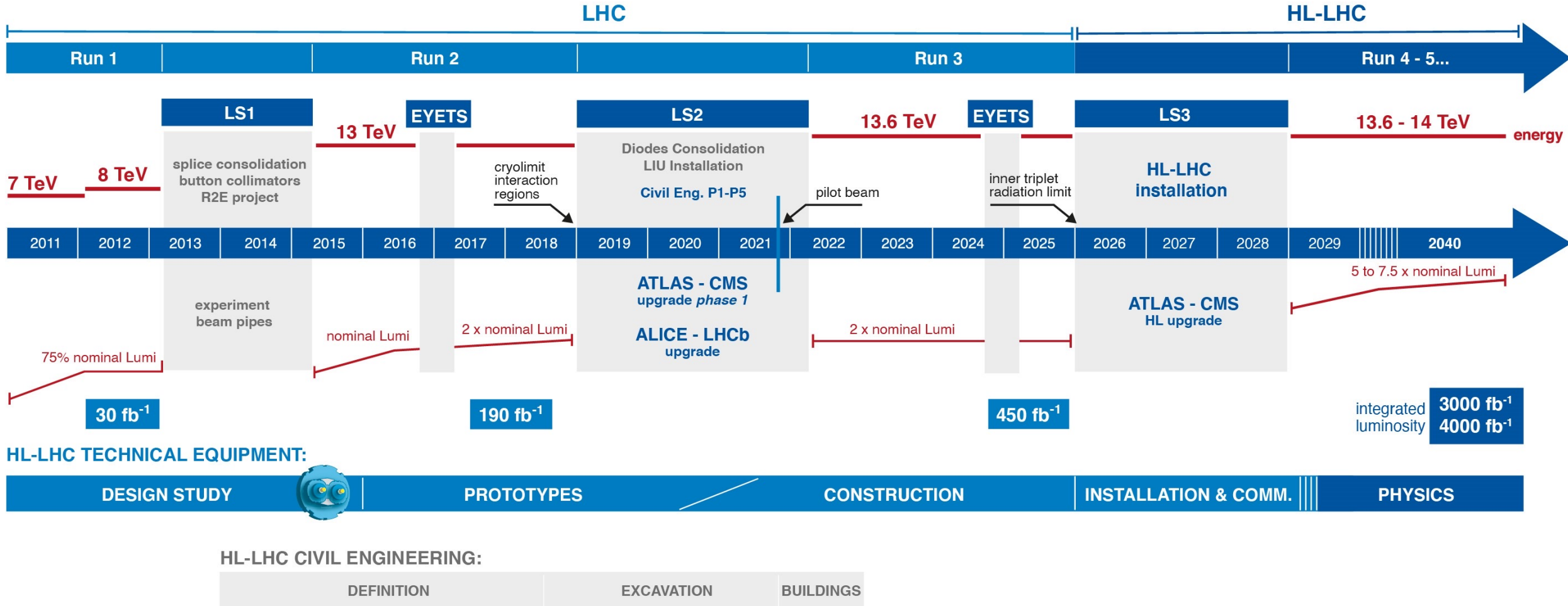
<https://cds.cern.ch/record/2296612>

- Precision timing** with:
- Barrel layer: Crystals + SiPMs
  - Endcap layer: Low Gain Avalanche Diodes



# The timeline

LHC/ HL-LHC Plan (last update February 2022)



We are in the end of 2022. Most of the detector upgrades will be installed in 2026 or shortly after. **2022-2026 is crucial (assembly and QA/QC)!**

# Upgrade projects with CMS-China involvements



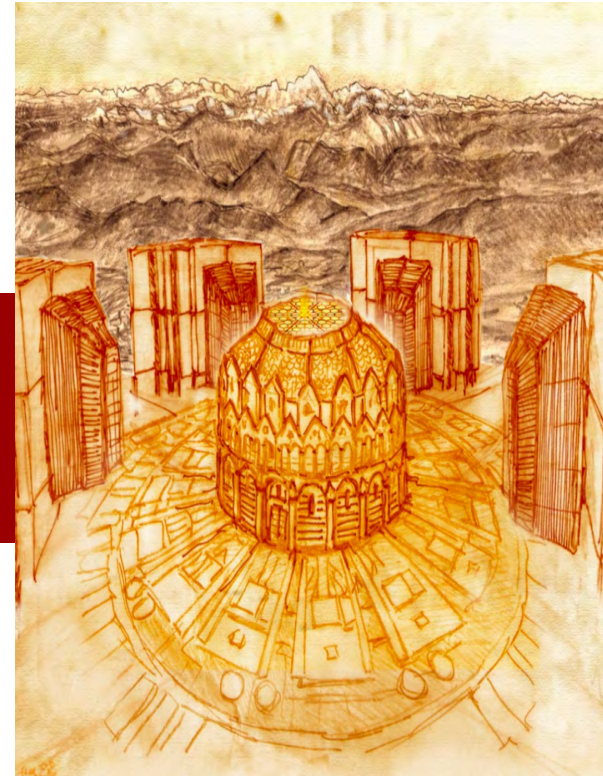
This talk will focus on the progresses mainly from CMS-China



**MUON  
GEM**



**Timing  
MTD**



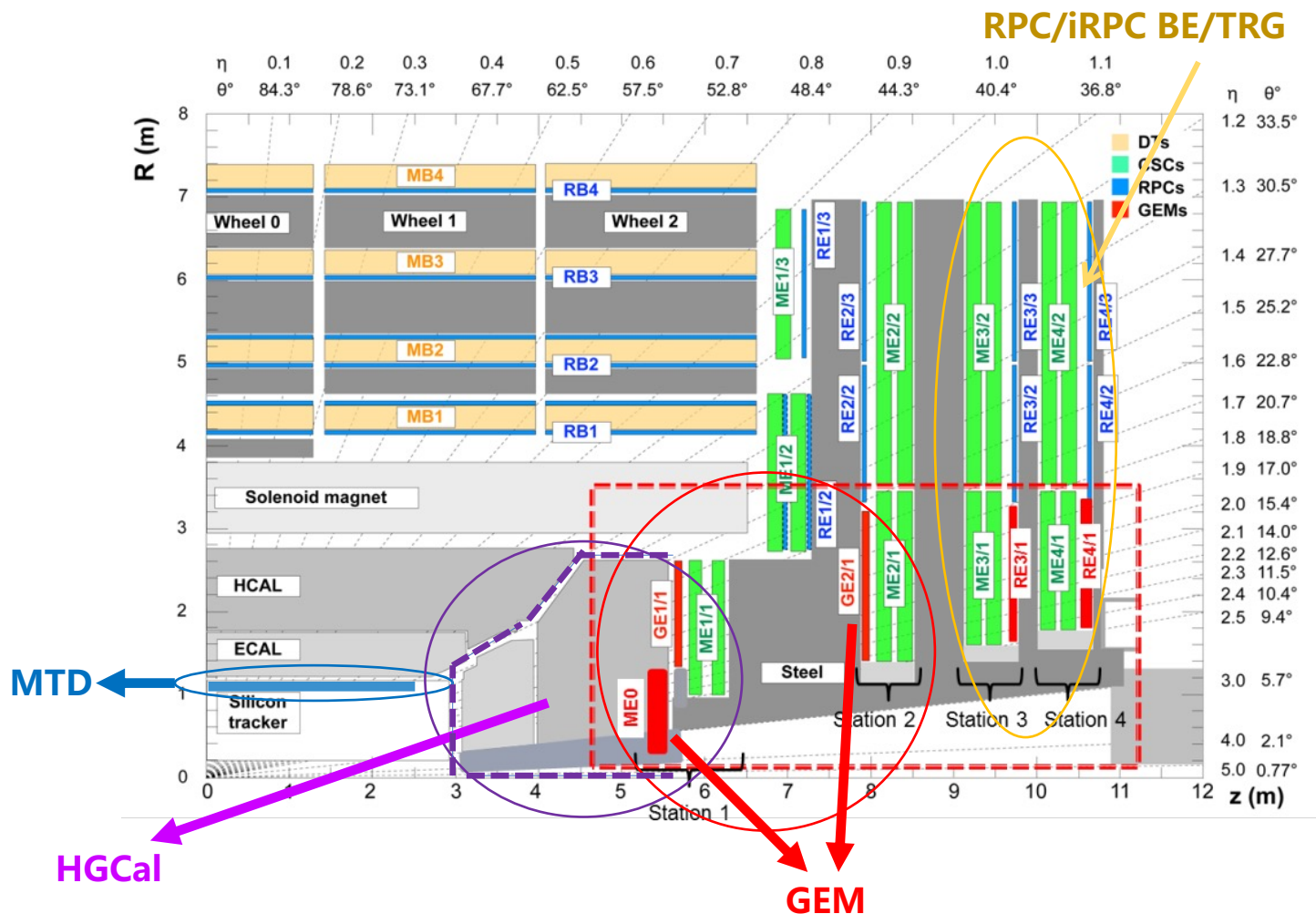
**Calo endcap  
HGCal**



**Trigger  
RPC/iRPC BE/TRG**

# Where do they sit?

The location of



Most of the projects are **close to the beam**

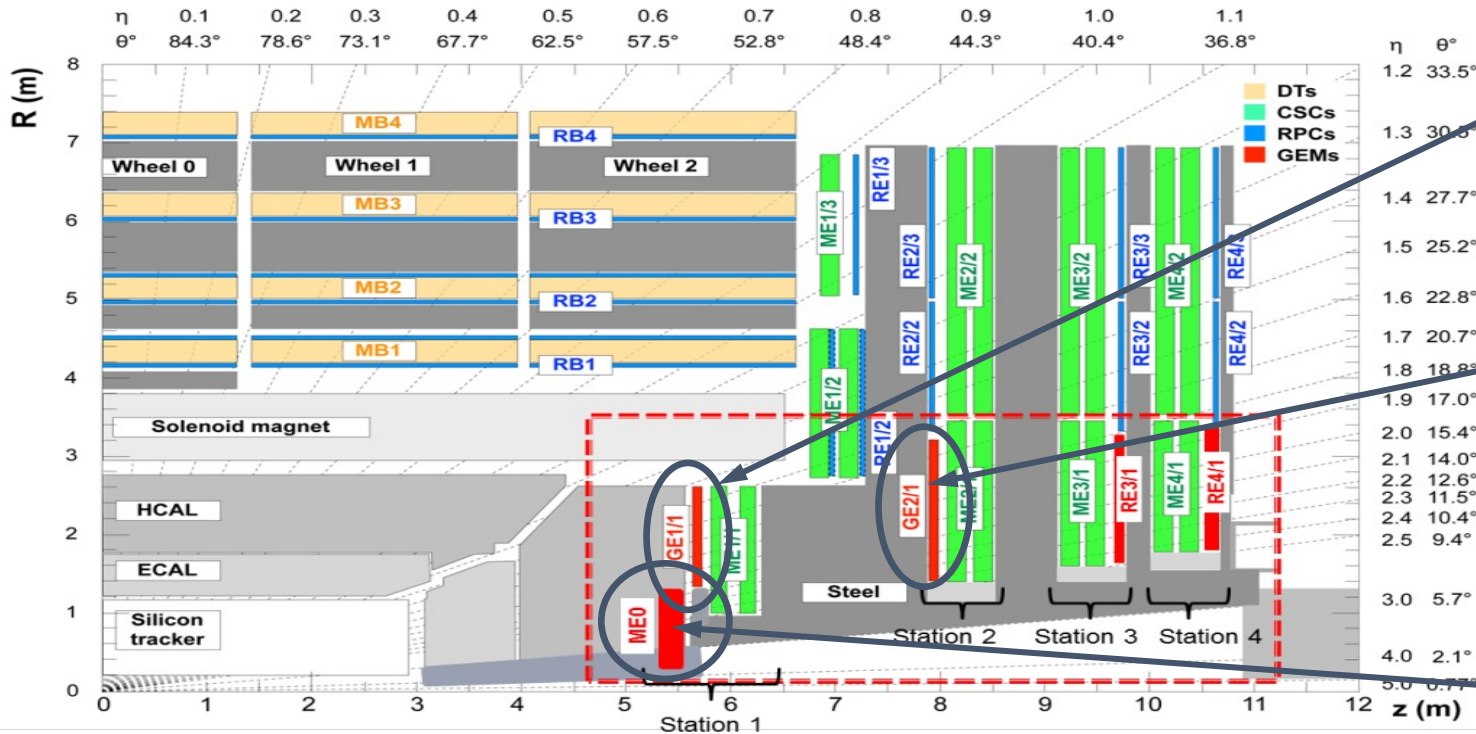
High **counting rate**

High **radiation**

# The GEM project

PKU+THU+SYSU+BUAA

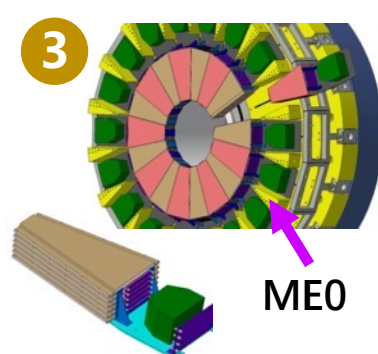
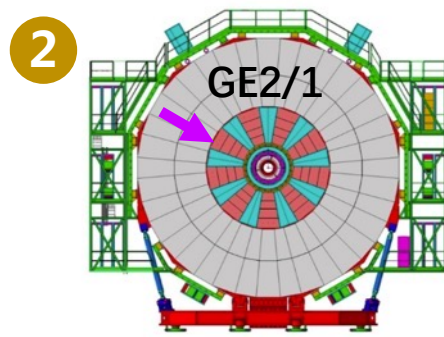
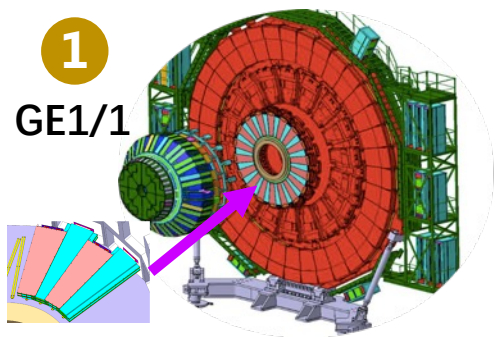
The three GEM stations



**1 GE1/1 GEM :** production of all GEM Electronics Boards (GEB) in China (completed!); assembly and commission Running in Run3

**2 GE2/1 GEM :** Design, R&D and production of all GEB in China ; production of  $\sim 1/8$  GEM at PKU, assembly and commission. Built 6 GEM detectors at PKU this Oct

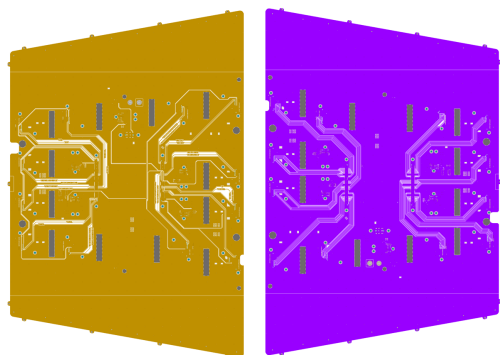
**3 ME0 GEM :** Design, R&D and production of all GEB in China ; production of  $\sim 1/5$  GEM at PKU, assembly and commission



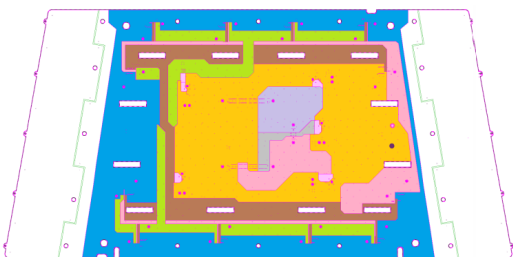
# GE2/1 GEB

R&D and production of CMS-GEM GE21 Electronics boards

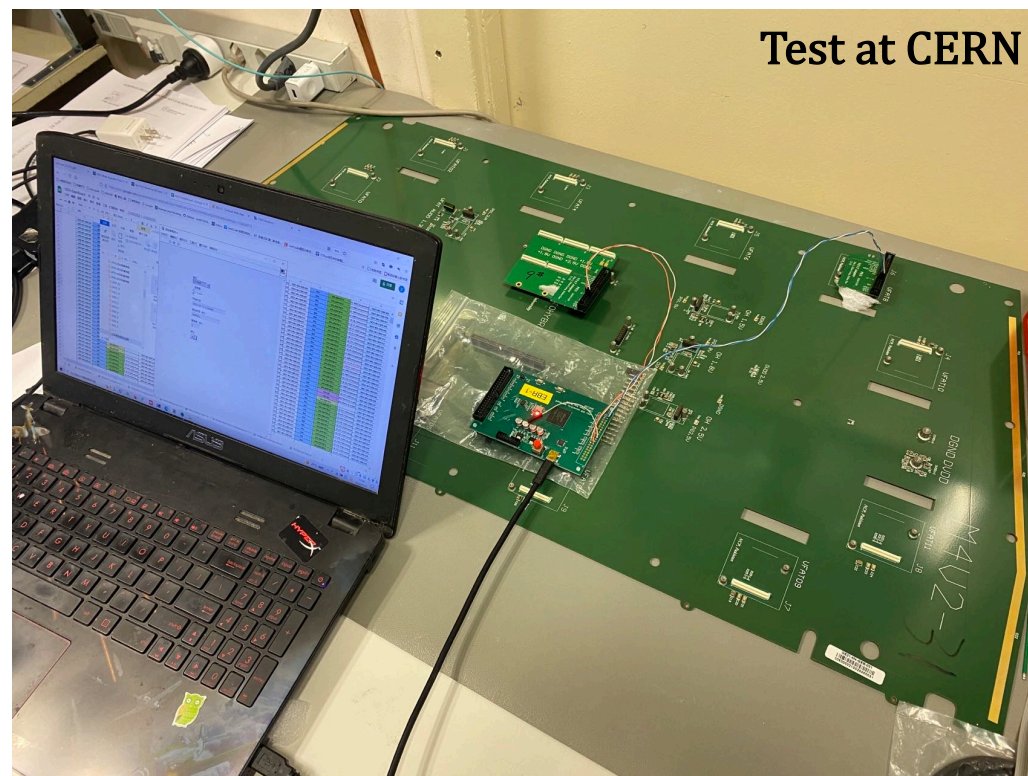
- Completed design of GE2/1 GEB, including the **signal transmission** (12 VFAT trigger unit & characteristic impedance matching), **power distribution** system (5 FEAST for VFAT), mechanical design, **power monitor** system
- Completed **tests in Shenzhen** (PKU & SYSU) this summer
- Completed **tests at CERN** this summer



Signal transmission system



Power distribution system



Test at CERN



Test in Shenzhen



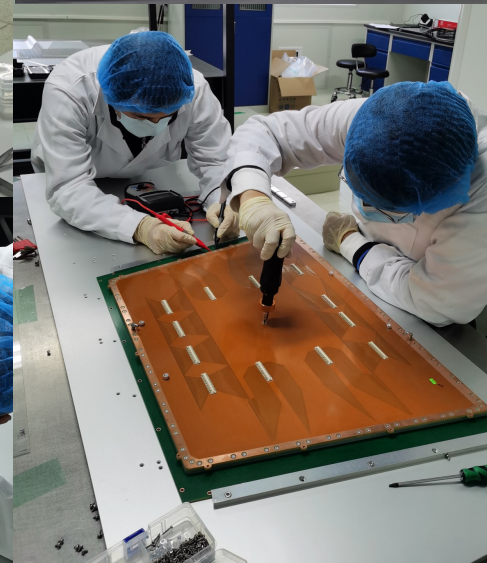
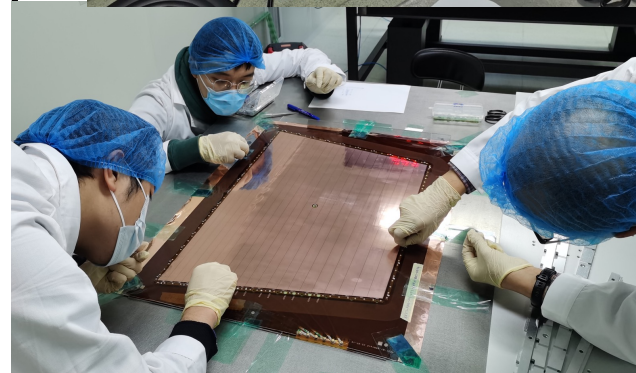
# GE2/1 detector assembly

Mass production at PKU NOW!

- This is the first Phase-II mass production of the full-sized detector in China!
- Assembly of GE2/1 in PKU started:
  - 6 GE2/1 M5 GEM have been assembled this October
  - In total, 1/8 GE2/1 (37 pieces) will be assembled at PKU
  - QC3, QC4 and some part of QC5 tests will be done in PKU



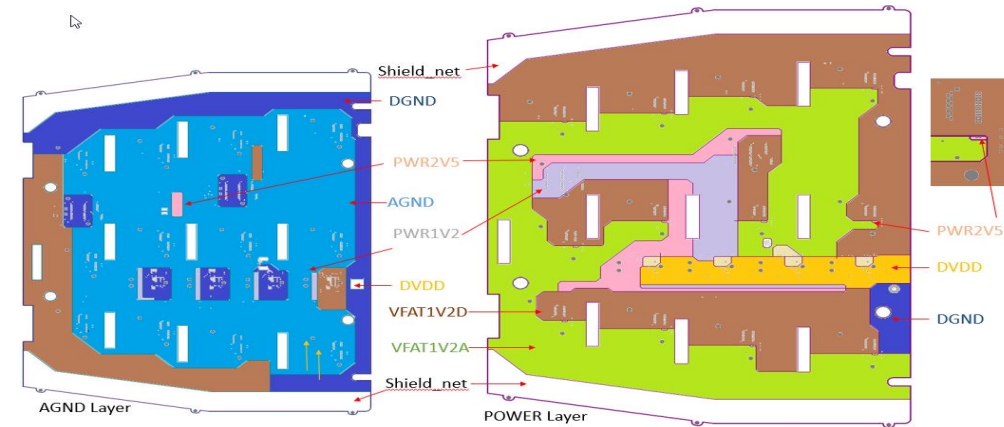
Born at PKU



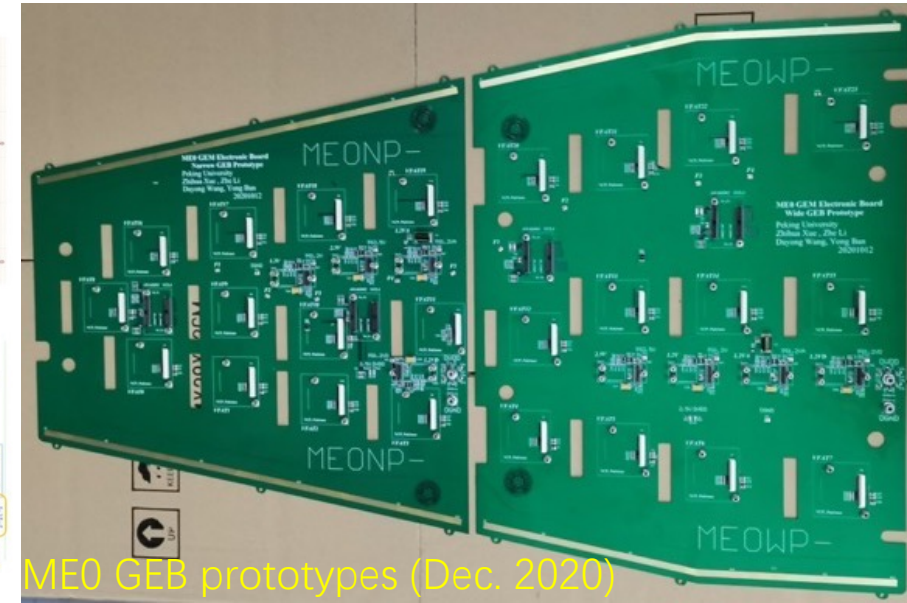
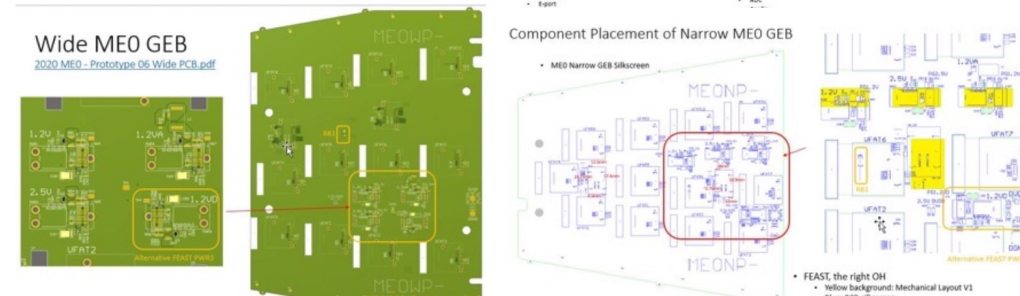
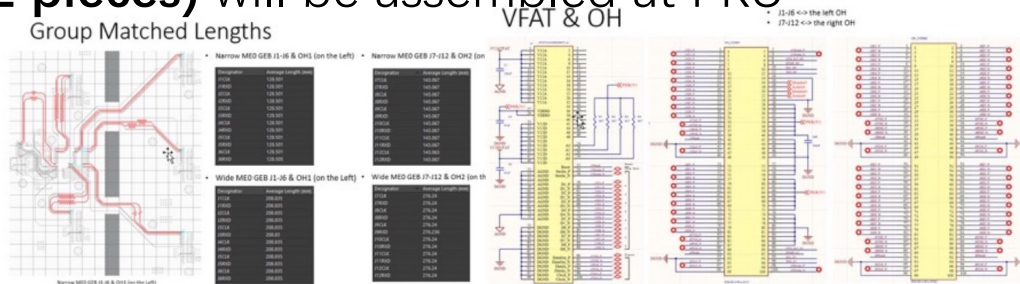
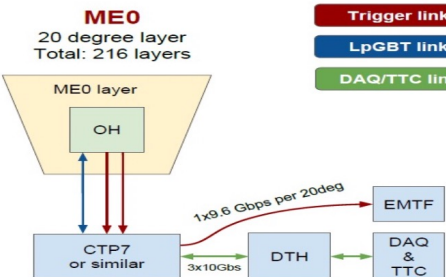
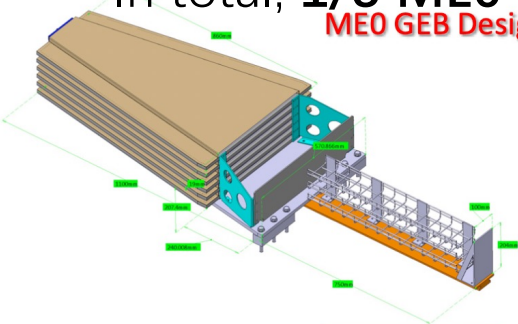
# ME0 GEB

Design and R&D

- The design of the 1st version of ME0 GEB by PKU group was completed, reviewed and validated by CMS-GEM collaboration
- The 1<sup>st</sup> prototypes of 7 sets were produced, shipped to CERN&USA in Feb. 2021, and have shown excellent test results
- Later 2022, ME0 GEB mass production is expected
- In total, **1/5 ME0 (42 pieces)** will be assembled at PKU



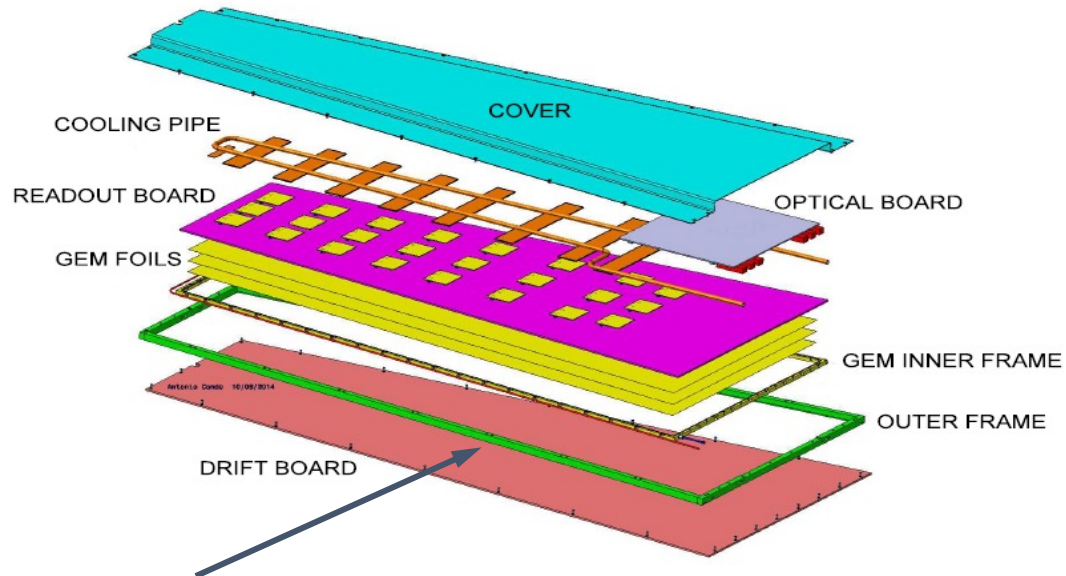
Power distribution



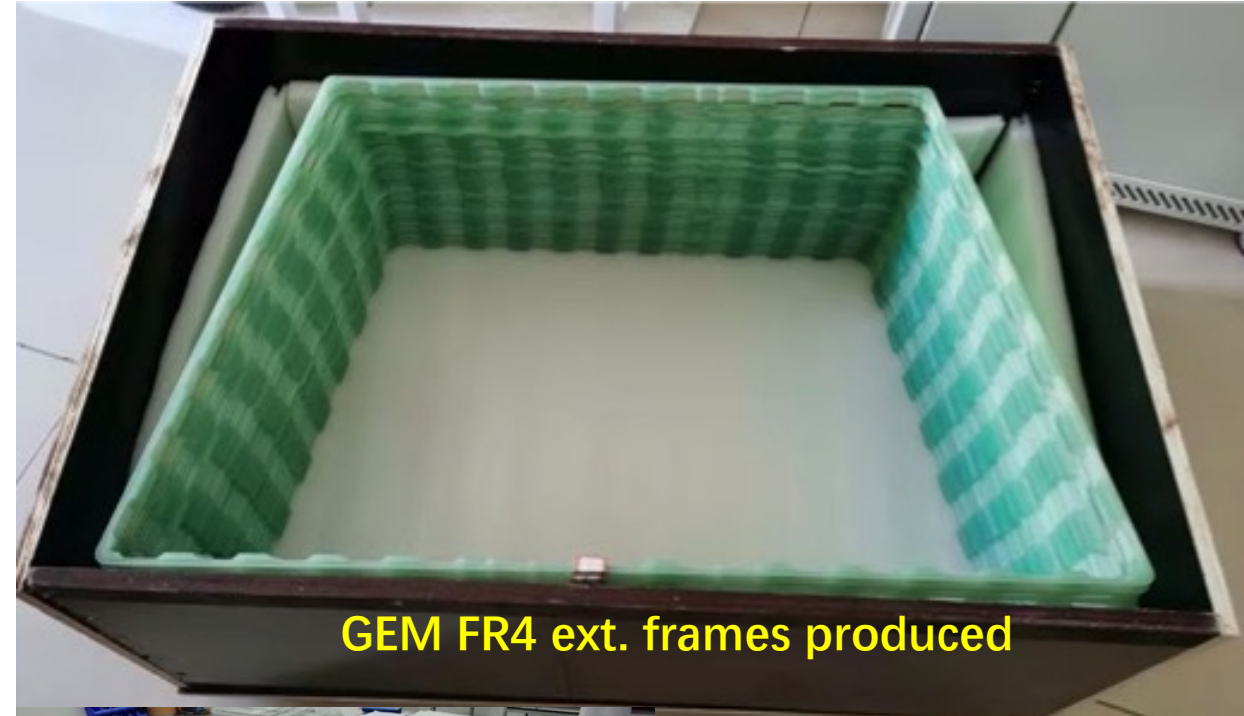
# External Frames and SM Structures

R&D and production

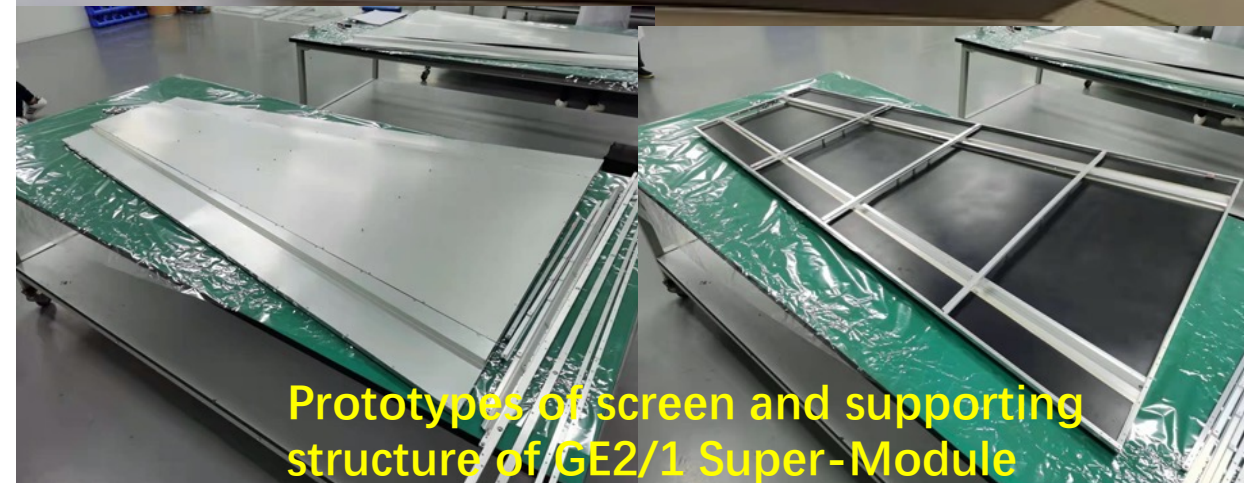
- **GEM External Frame:** fabricated with FR4 materials with very **high precision** (tolerance on thickness < 0.03 mm)
  - Production of all GE2/1 FR4 external frames (320 sets) completed, tested and shipped to CERN May 2021
- **Screen and supporting structure** of GE2/1 Super-Module (SM): 2 types ( $\sim 1 \times 2 \text{m}^2$ ) holds 8 GEM chambers (M1-M8), providing mechanical support, insulation, screening
  - Started mass production early 2022



**GEM external frames (FR4): extremely high requirements on mechanical tolerance**



**GEM FR4 ext. frames produced**

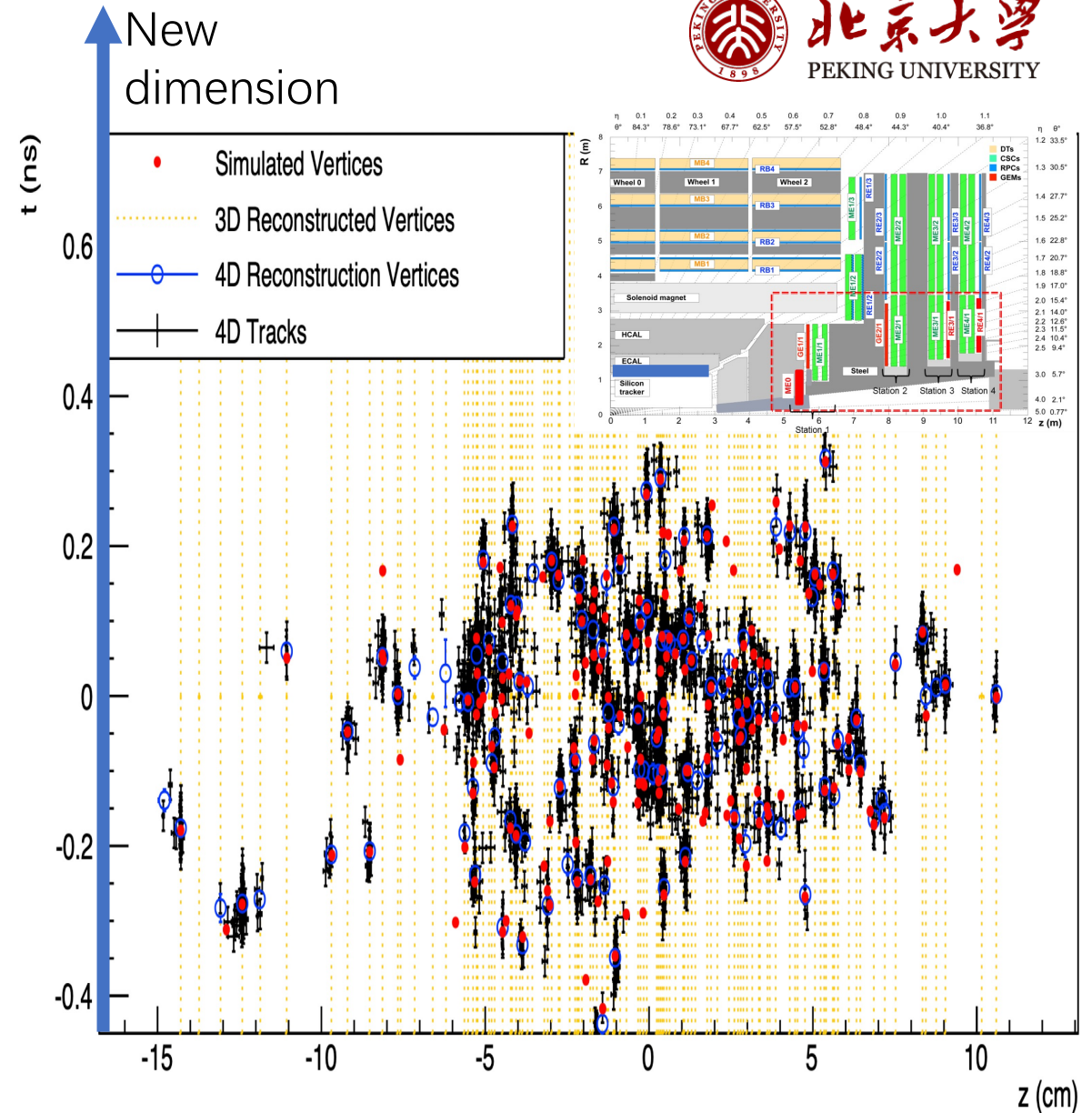


**Prototypes of screen and supporting structure of GE2/1 Super-Module**

# The MTD Project PKU+THU+BUAA

## The motivation

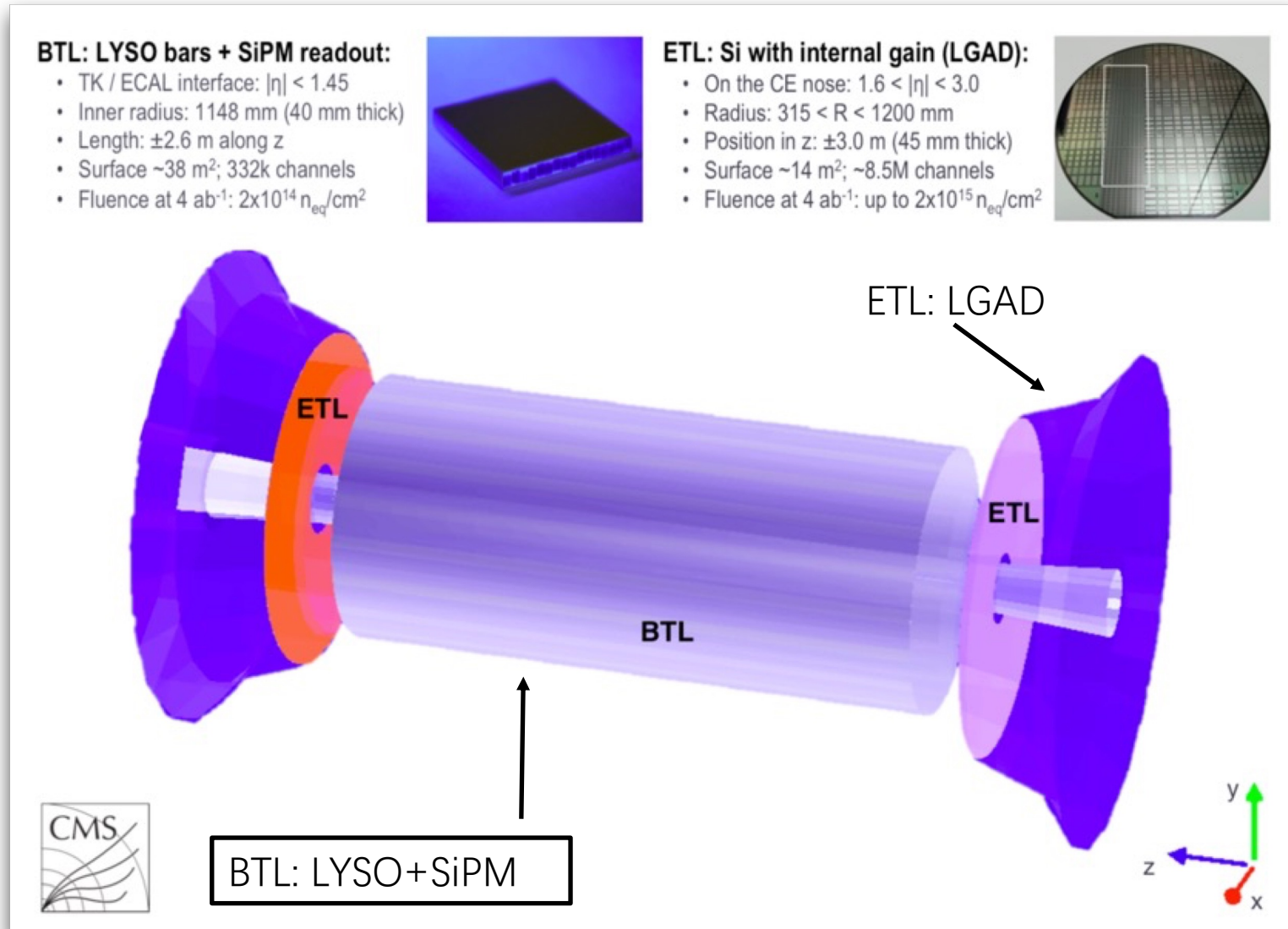
- At HL-LHC, the instantaneous lumi is  $\sim 4x$  of the current one
  - Faster accumulation of data
  - **BUT severe pileup**
- Demand a good separation of pileup and interested vertices
  - Improve further the spacial resolution to a next level
  - NEW idea: introduce time information of the particles
- This new idea bring CMS a new detector called **MTD (MIP timing detector)**
- Time info provides a brand **new dimension** to use in identifying the pileup vertices
  - Assuming a **time resolution of 30 ps**, then one can make 6-7 bins in the y-axis on top of the spacial separation of the vertices
  - Big impact on physics in HL-LHC (Higgs, HH, SUSY, LLP, flavor physics etc.)



# The MTD Project

## The overview

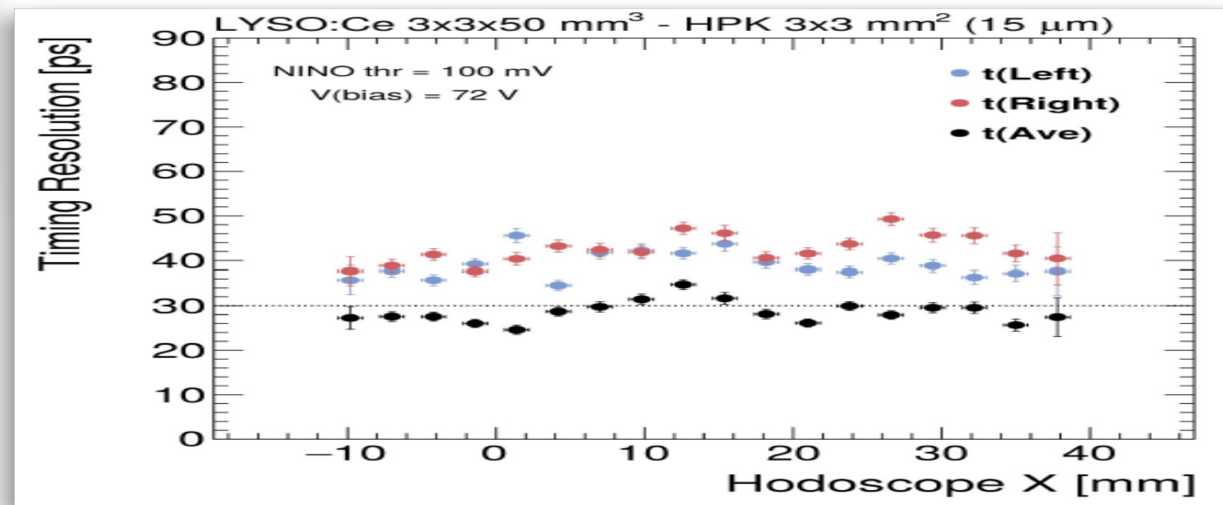
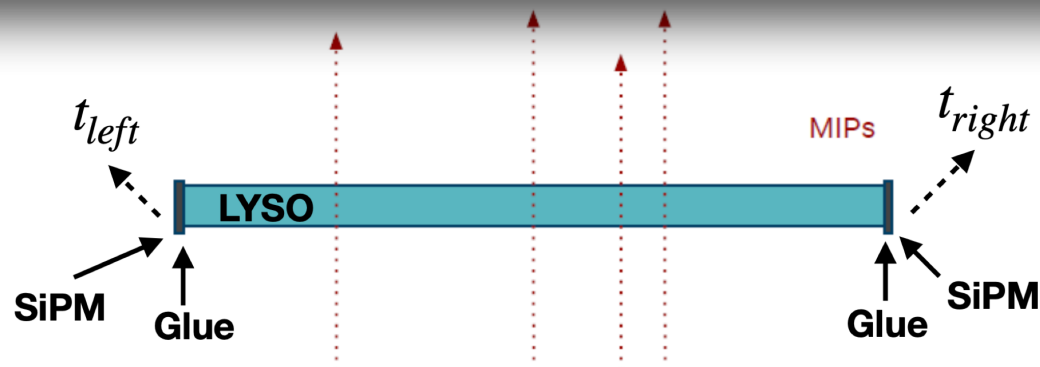
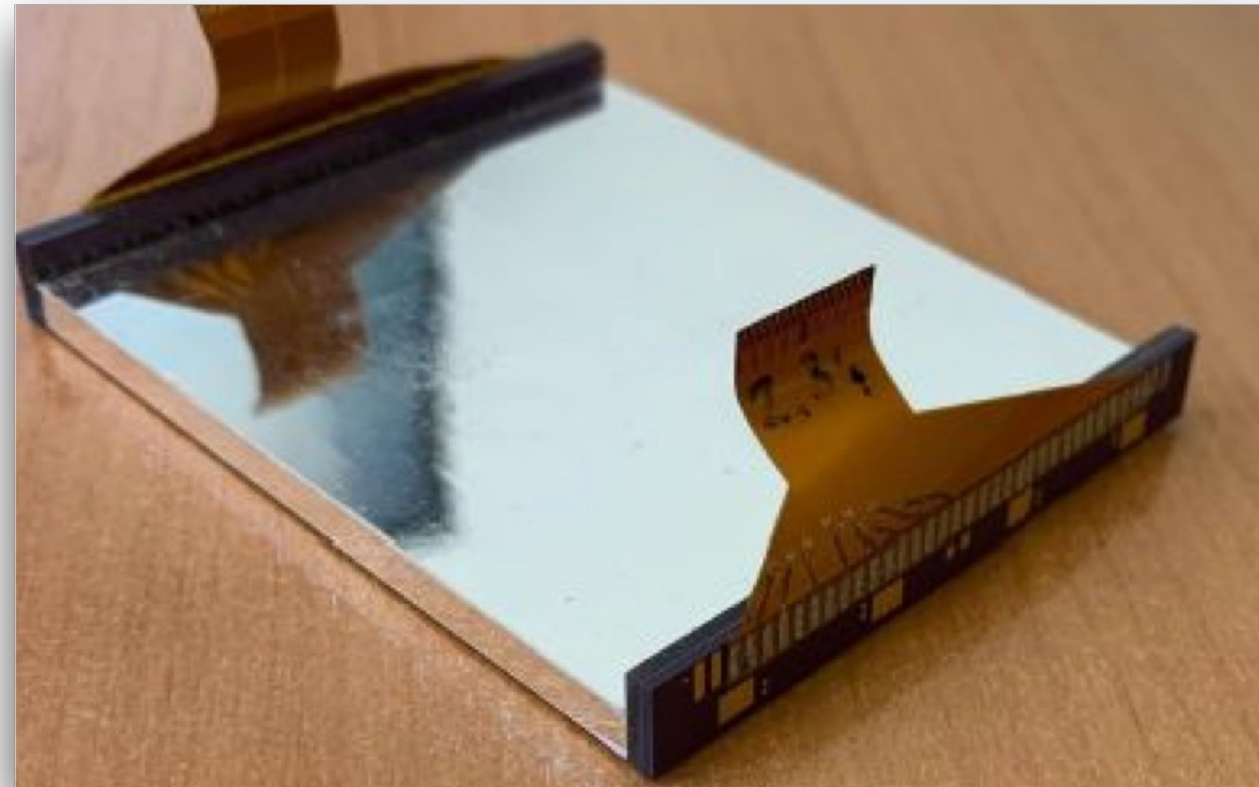
- The MTD detector is designed to head for a time resolution of **30 ps** in both barrel and endcap
- MTD will be install between the tracker and ECAL, and shares the same dry/cold volume with the tracker
  - MTD is **compact** enough to fit the cooling chamber in the track and leave **negligible impact** to the downstream calorimeter
- MTD is composed of the barrel (BTL) and the endcap (ETL)
  - BTL uses **LYSO + SiPM** duel readout
  - ETL uses **LGAD**
- BTL covers up to  $|\eta| < 1.45$ 
  - Surface  $\sim 38 \text{ m}^2$
  - Inner radius  $\sim 1.2\text{m}$ , length  $\pm 2.6\text{m}$
  - 332k channels (SiPMs)
- In this talk, we will focus on BTL which China MTD mostly focuses on at the moment



# The sensor

LYSO + SiPM

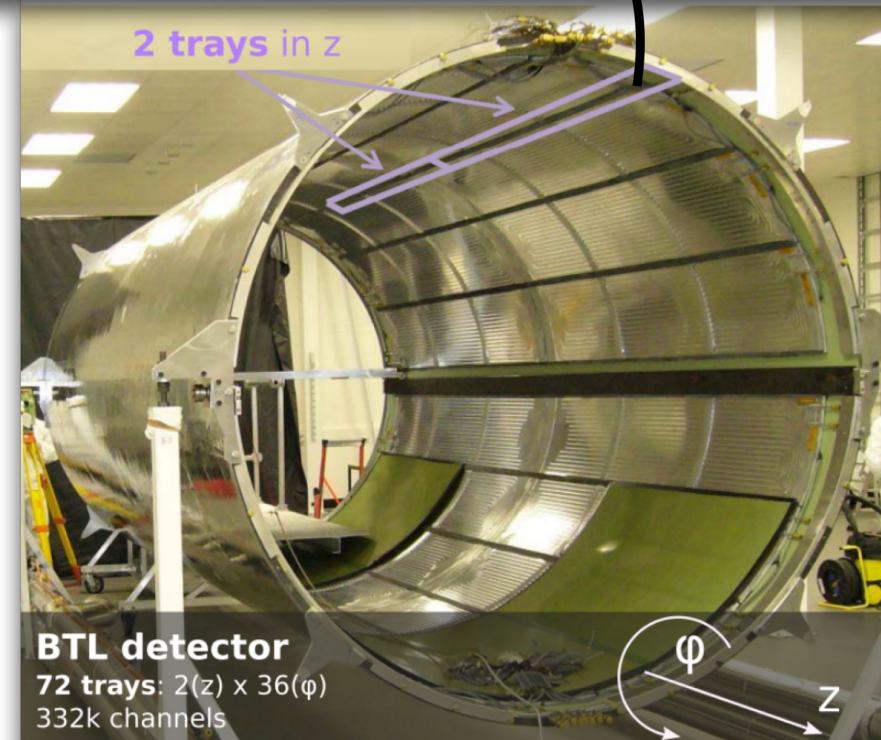
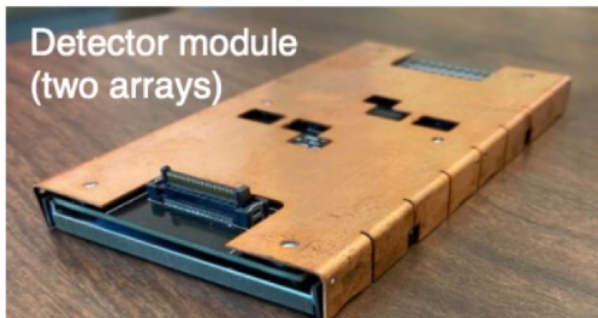
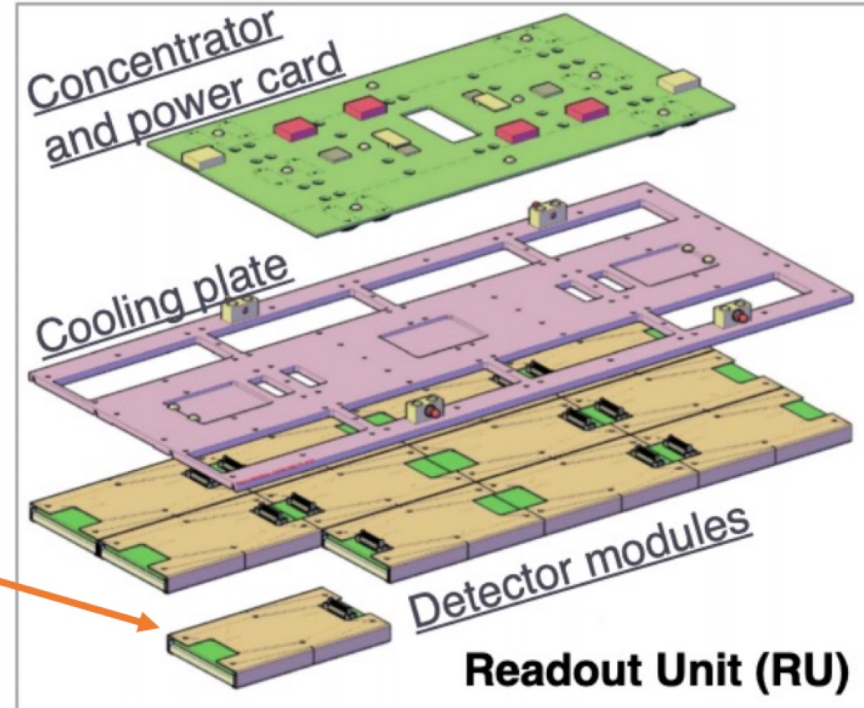
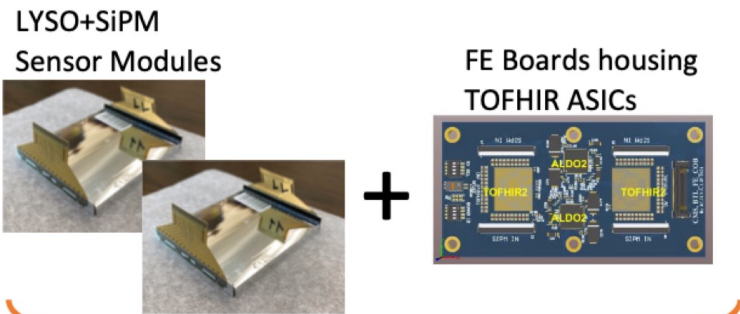
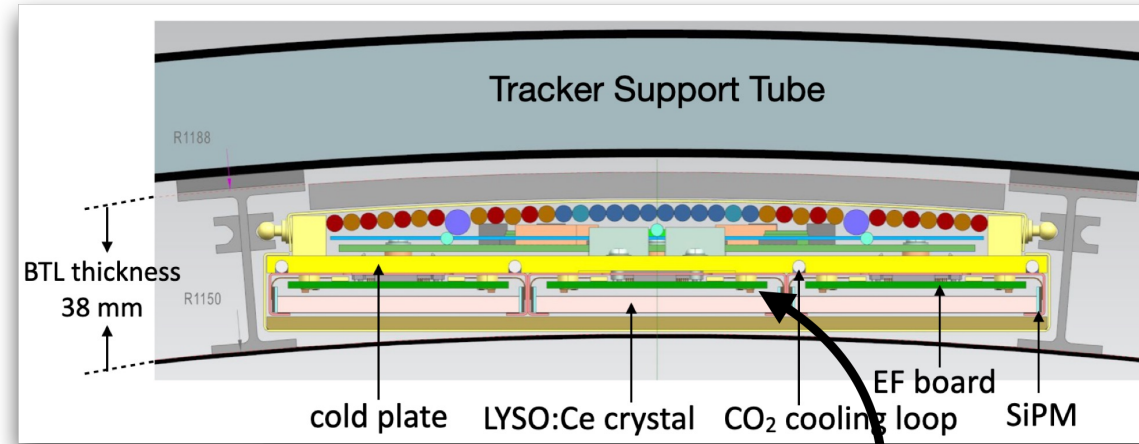
- Sensor module has **16 LYSO** bars ( $3 \times 3 \times 57$  mm<sup>3</sup>)
  - High light yield ( $\sim 40000$  photons/ MeV)
  - Fast scintillation rise time ( $< 100$  ps)
  - Short decay time ( $\sim 40$  ns)
- Dual readout by **2 SiPM** arrays
  - Photo-detection efficiency (PDE): 20-40%, with optimal cell size of  $15 \mu\text{m}$
  - Gain:  $1.5\text{-}4 \times 10^5$
- Cooled to  $-35$  to  $-40^\circ\text{C}$  with CO<sub>2</sub> and  $-10^\circ\text{C}$  with thermo-electric cooler (TEC)
- The time resolution can reach 30 ps regardless of the position of inducing particles



# The assembly

Sensor module – detector module - readout unit - tray

- BTL detector mounted on inner surface of Tracker Support Tube (TST) and share the cooling
- **Sensor Modules (SM):** LYSO+SiPM & TEC
- **Detector Modules (DM):** SMs+FE
- DMs are grouped in **Readout Units (RU)**
- Mechanical support & CO<sub>2</sub> via cooling plate in a **Tray**
- **We got approved to build a MTD BTL assembly center**

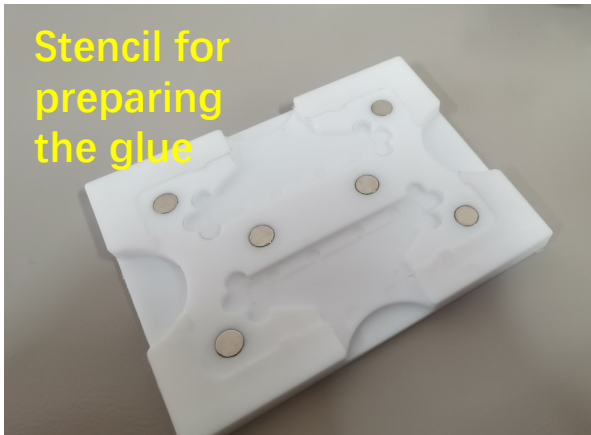
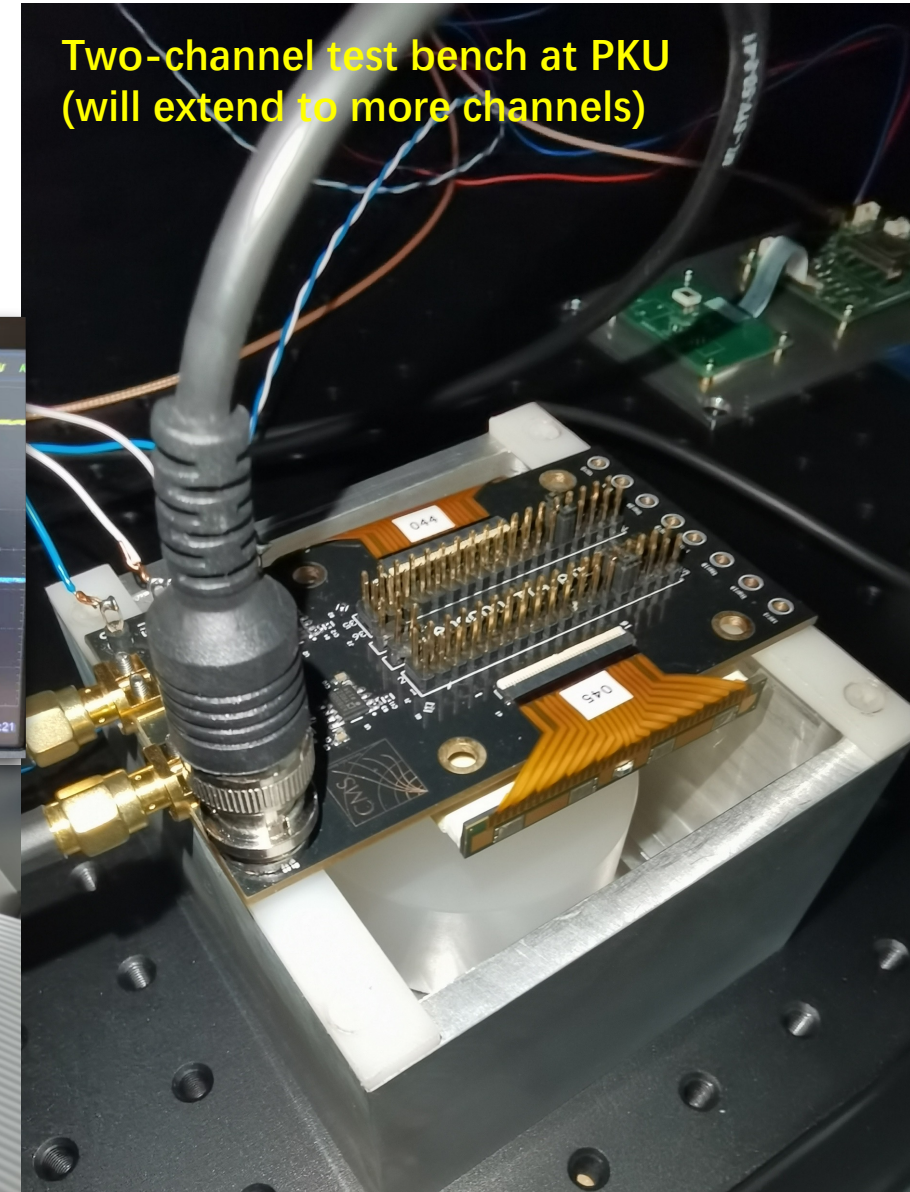


# Local preparation of the assembly center

PKU lab activities

- Actively preparing the assembly center
- Improving the tool for **coupling the LYSOs and the SiPMs**
- Setting up **the test bench for the sensor modules**

Two-channel test bench at PKU  
(will extend to more channels)



Stencil for preparing the glue



Bonding station



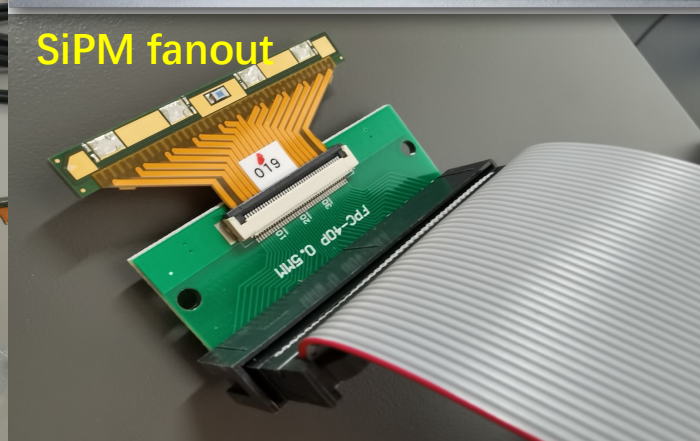
Typical signals from self-radiation of LYSO



Gluing mask



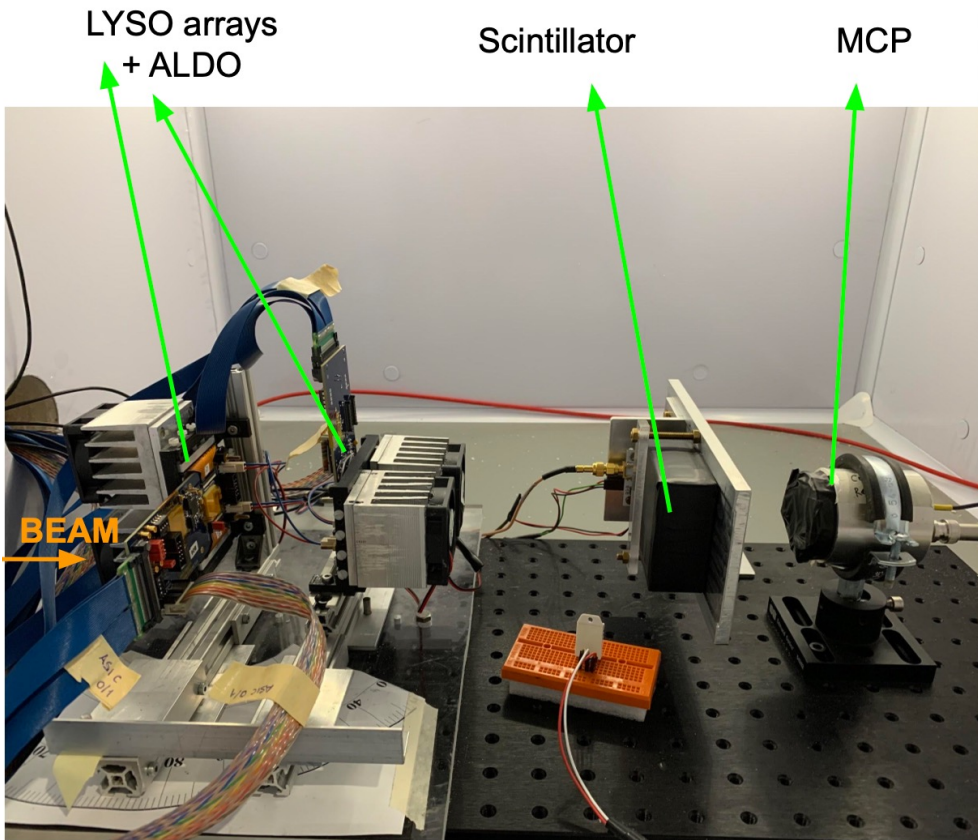
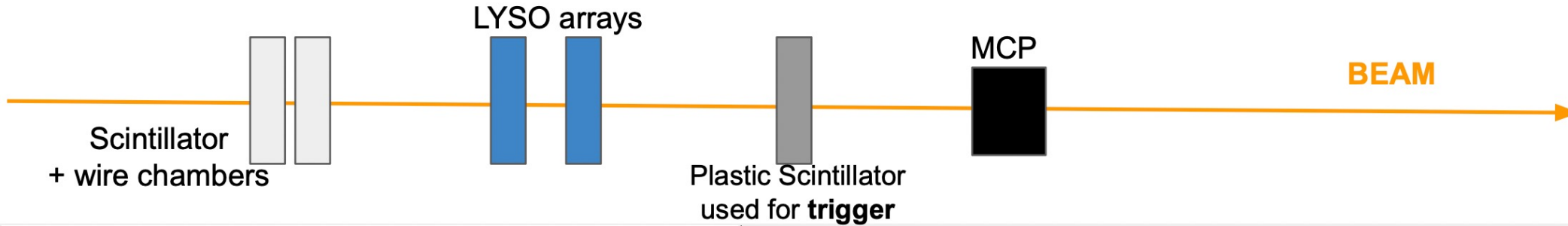
SiPM fanout



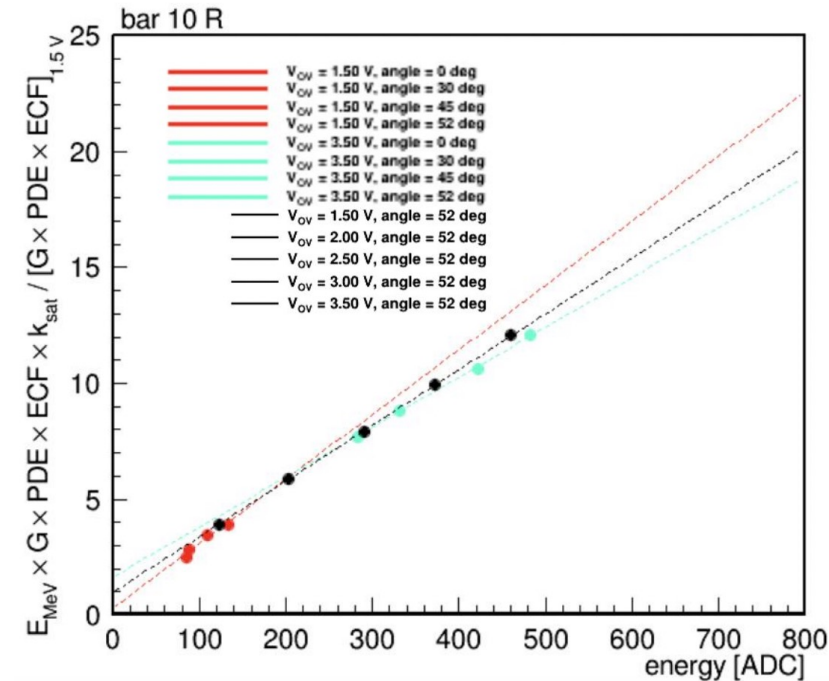
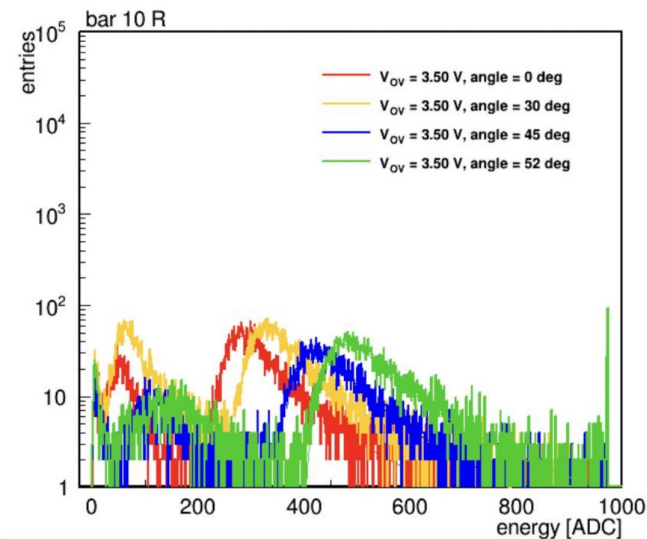


# MTD BTL test beam studies

Test beam at H8



- Participate test beam studies
- Focus on the **energy linearization**, varying the angle,  $V_{ov}$ , temperature and the irradiation



# The HGCal project

A 5D calorimeter

Demand high granularity detector in the forward region for PF jets, VBF topology and highly-boosted jets (W/Z) at HL-LHC

**HGCal (High Granularity Calorimeter)** will replace its endcap calorimeters

## Active Elements:

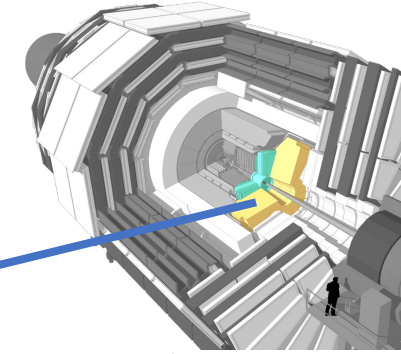
- **Si sensors** (full and partial hexagons) in CE-E and high-radiation region of CE-H.
- **SiPM-on-Scintillating tiles** in low-radiation region of CE-H

Electromagnetic calorimeter (**CE-E**): **Si**, Cu/CuW/Pb absorbers, 28 layers,  $25.5 X_0$  &  $\sim 1.7\lambda$

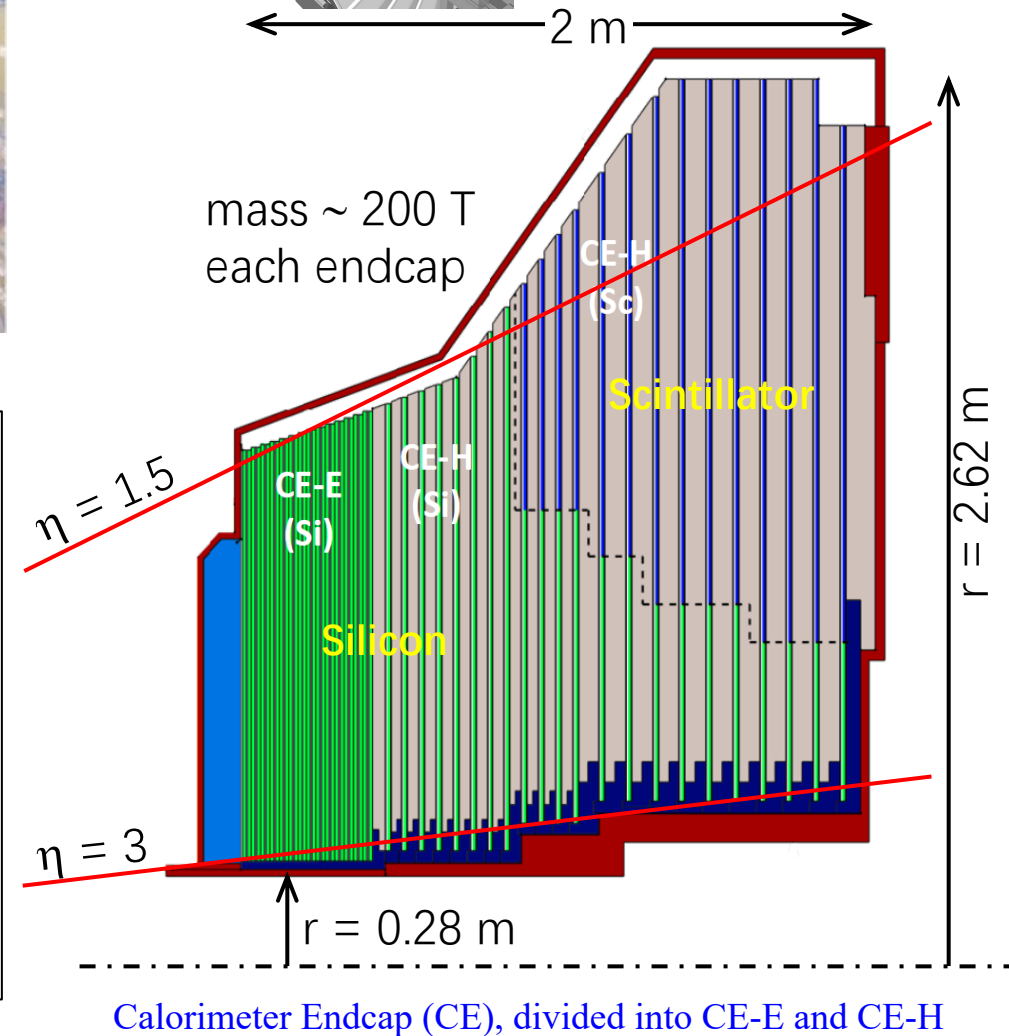
Hadronic calorimeter (**CE-H**): **Si** & **scintillator**, steel absorbers, 22 layers,  $\sim 9.5\lambda$  (including CE-E)

## Key Parameters (updated from the TDR):

- HGCal covers  $1.5 < \eta < 3.0$
- Full system maintained at  $-30^\circ\text{C}$
- $\sim 640 \text{ m}^2$  of silicon sensors  $\sim 3x$  tracker
- $\sim 370 \text{ m}^2$  of scintillators
- 6.1M Si channels, **0.5 or 1.1 cm<sup>2</sup> cell size** (6M)
- 240k scint-tile channels ( $\eta$ - $\phi$ )
- Trigger readout from alternate layers in CE-E and all in CE-H
- $\sim 31000$  Si modules (incl. spares)



北京大学  
PEKING UNIVERSITY



# The HGCal project

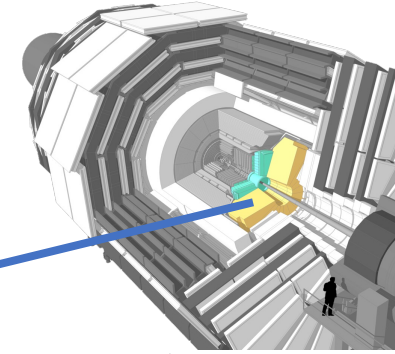
A 5D calorimeter

Demand high granularity detector in the forward region for PF jets, VBF topology and highly-boosted jets (W/Z) at HL-LHC

HGCal (High Granularity Calorimeter) will replace its endcap calorimeters



The existing endcap calo



北京大学  
PEKING UNIVERSITY

## Active Elements:

- Si sensors (full and partial hexagons) in CE-E and high-radiation region of CE-H.
- SiPM-on-Scintillating tiles in low-radiation region of CE-H

Electromagnetic calorimeter (CE-E): Si, Cu/CuW/Pb absorbers, 28 layers,  $25.5 X_0$  &  $\sim 1.7\lambda$

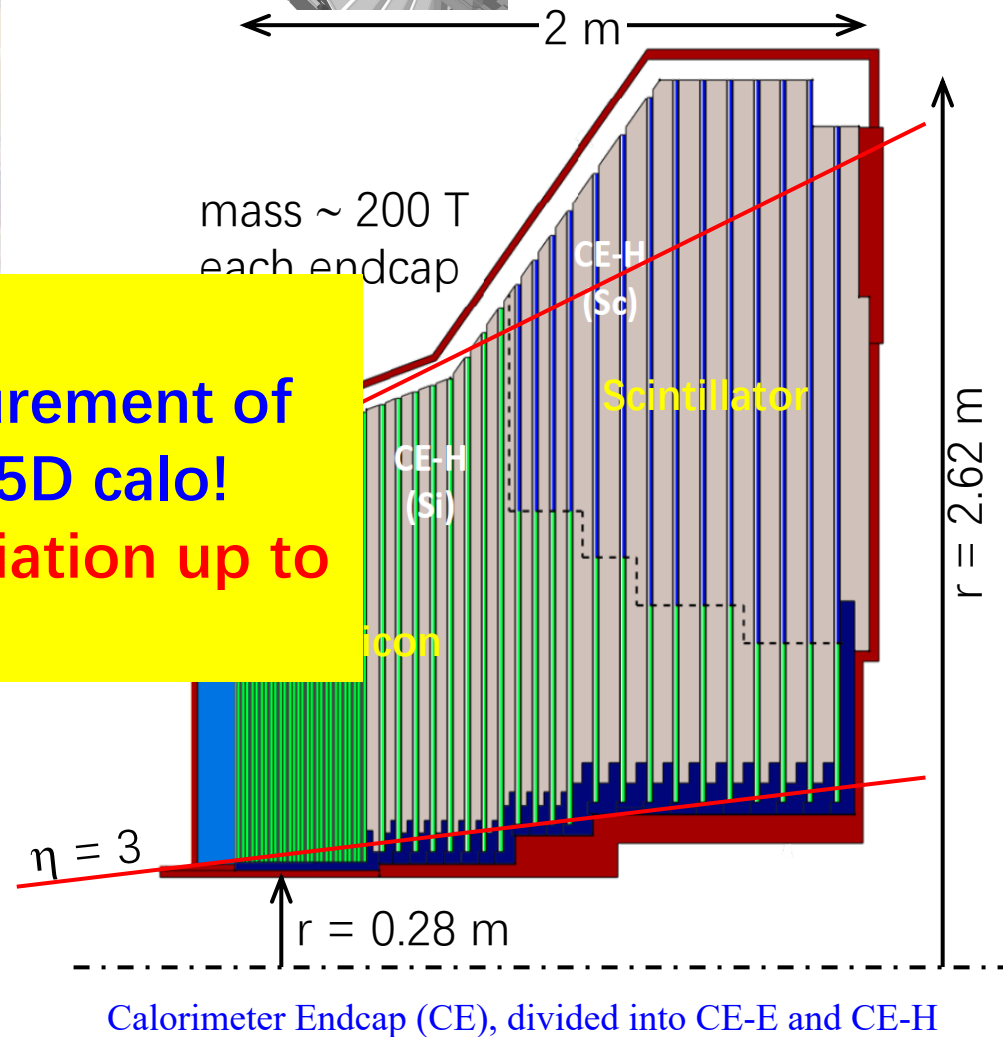
Hadronic calorimeter (CE-H): Si & scintillator, steel absorbers, 22 layers,  $\sim 9.5\lambda$  (including CE-E)

Readout granularity is  $1 \text{ cm}^3$

Providing simultaneous measurement of energy, 3D position and time: 5D calo!

Stable performance after irradiation up to  $10^{16} n_{eq}/\text{cm}^2$

- 6.1M Si channels, 0.5 or 1.1  $\text{cm}^2$  cell size (6M)
- 240k scint-tile channels ( $\eta-\phi$ )
- Trigger readout from alternate layers in CE-E and all in CE-H
- **$\sim 31000$  Si modules** (incl. spares)



# Module Assembly Centers (MAC)

The IHEP MAC site was officially certified by CERN!



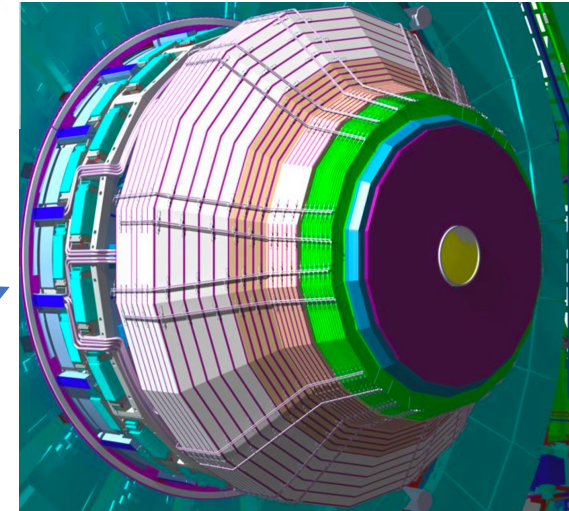
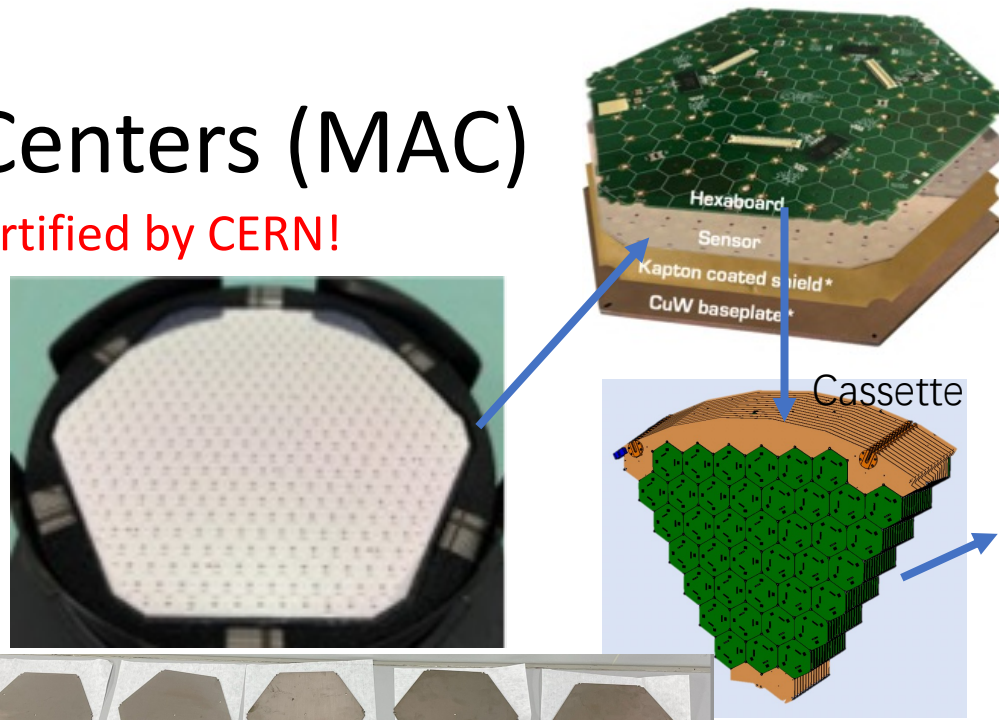
Silicon sensors are sandwiched with electronic boards and CuW base plates to form a **hexagonal module**, which will be tiled and stacked to make a cassette

**5 MACs** are now qualified

- UCSB, CMU, TTU, Taiwan, **IHEP** Beijing
- Setting up No. 6 at TIFR, good progress
- Each taking **5000 modules**

Alternative suppliers for **CuW** base plates

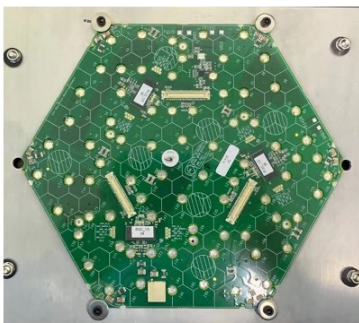
- Nominally Protvino deliverable
- Prototypes also made at KIT Karlsruhe, **IHEP** Beijing and TIFR Numbai



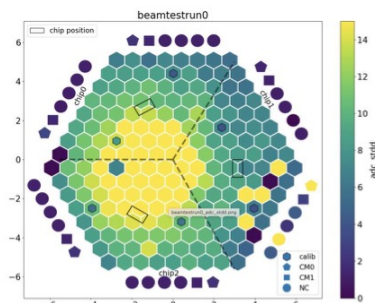
**IHEP provided CuW base plats**

**First 8in silicon model in CMS by IHEP**

**Certified MAC at IHEP**



**8in si model @ IHEP**



**CERN TB for this model**



**IHEP MAC team**



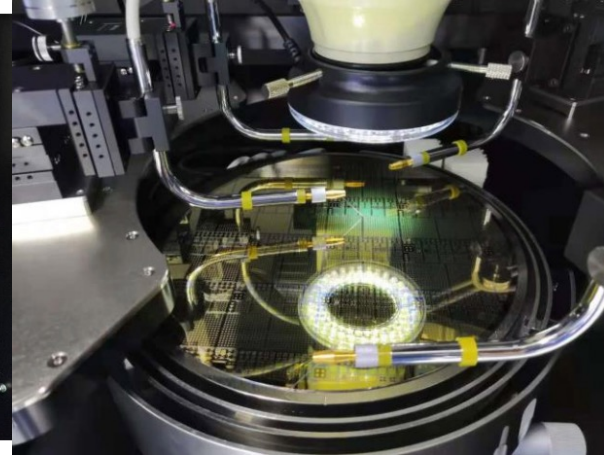
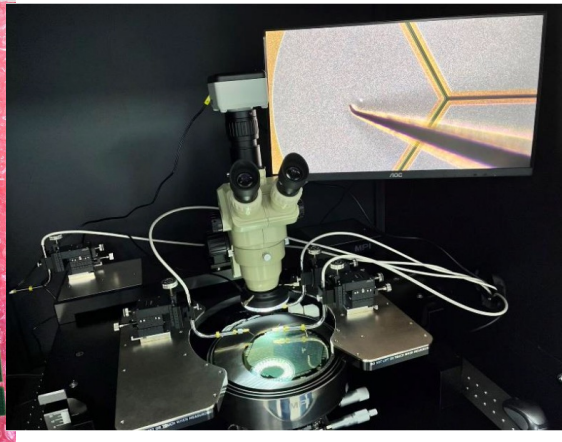
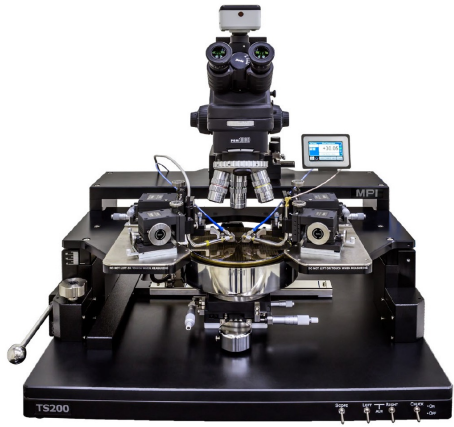
**The certification letter for the IHEP MAC site**



**Clean room @ IHEP**

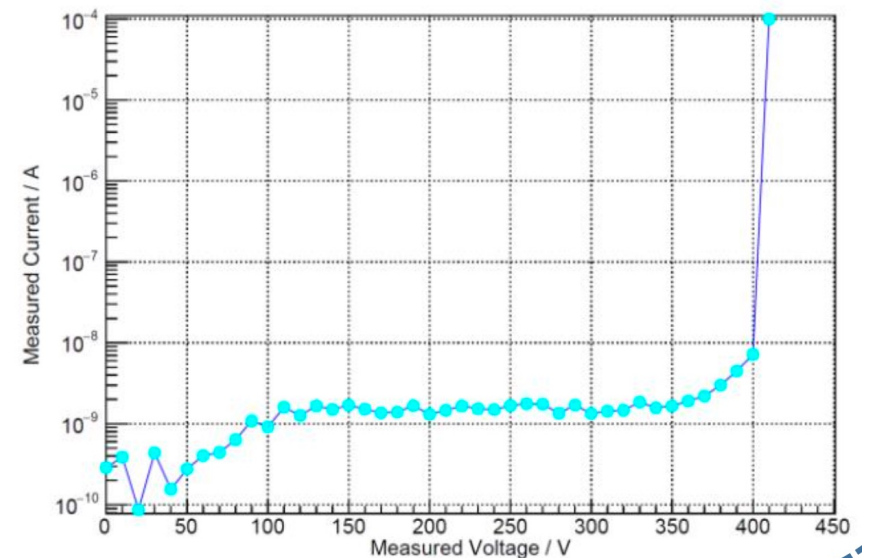
# NEW test bench for the silicon sensors

IHEP



- Participated the sensor testing at CERN
- Developed **the test bench locally at IHEP** for large areas of silicon sensor
  - Probe card
    - In place for 6 inch sensors (used for prototyping)
    - In plan to accommodate 8 inch sensors
  - Switch matrix
    - In place, 512 channels, can be used for both 6 and 8 inch sensors
  - Probe bench
    - Use probes to directly reach the sensors for the testing

Si-PIN Sensor IV Curve (Bias Polarity: Negative)



# A small **batch** production of 4 modules at IHEP



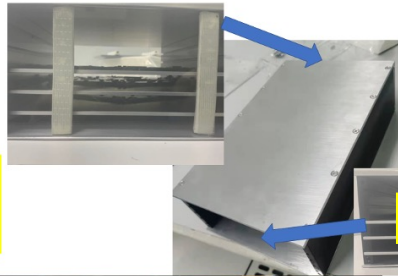
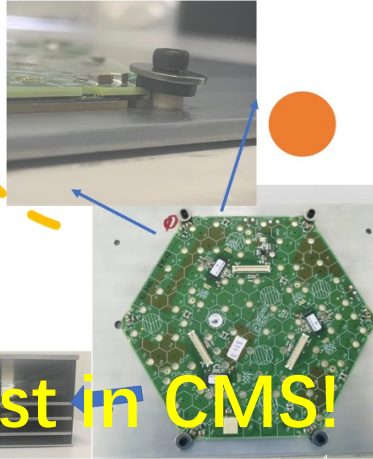
北京大学  
PEKING UNIVERSITY

Completed the first batch of 6 sensors in China, sent to Fermilab

2022  
Match  
to April

## sucessed small “mass” pre-production

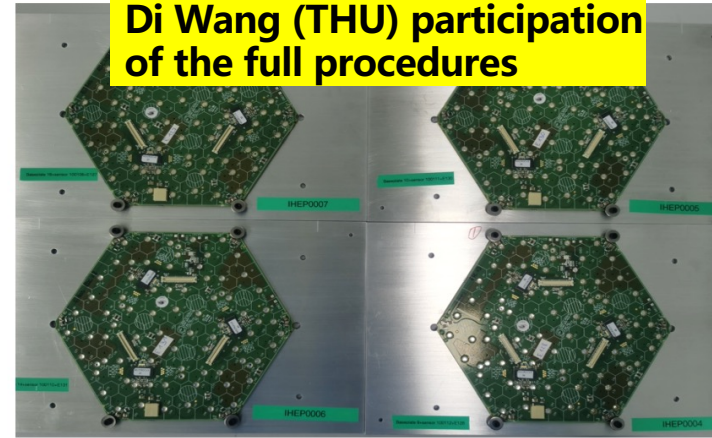
- 5 modules ship box
- Module mounted on carrier board
- Carrier board regulated by rubber



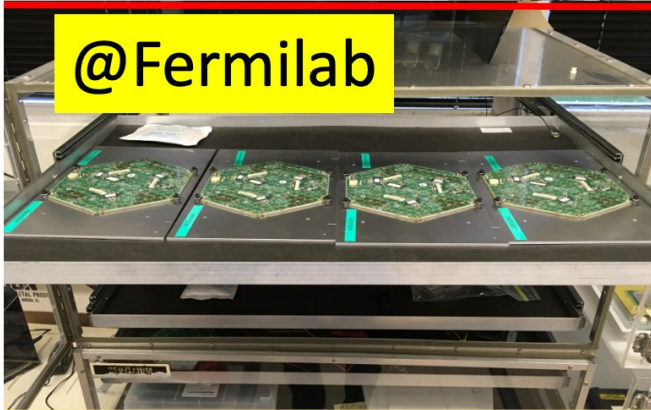
@IHEP

First in CMS!

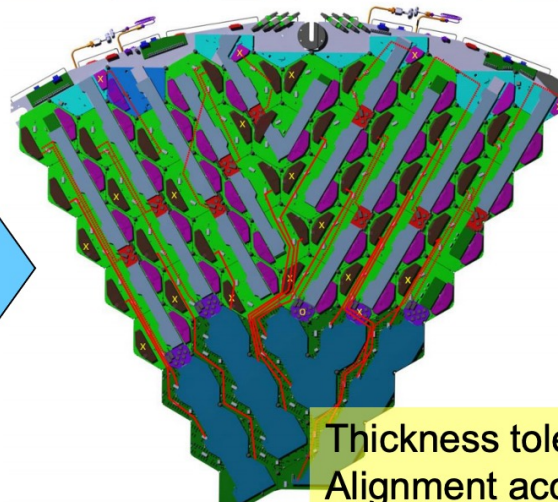
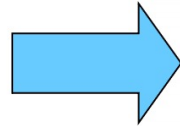
Di Wang (THU) participation  
of the full procedures



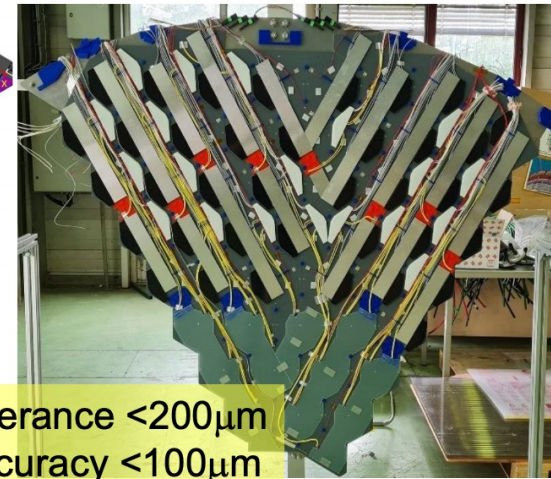
@Fermilab



4 Modules were accepted by Fermilab on 13 Apr.  
for **cassette** test

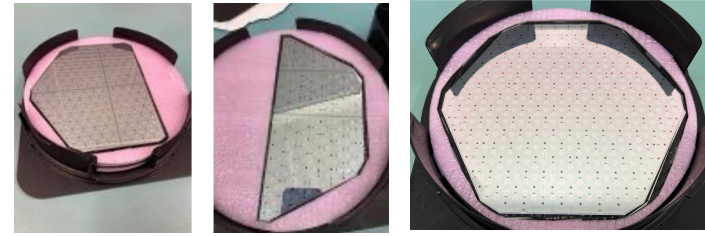


Thickness tolerance  $< 200\mu\text{m}$   
Alignment accuracy  $< 100\mu\text{m}$

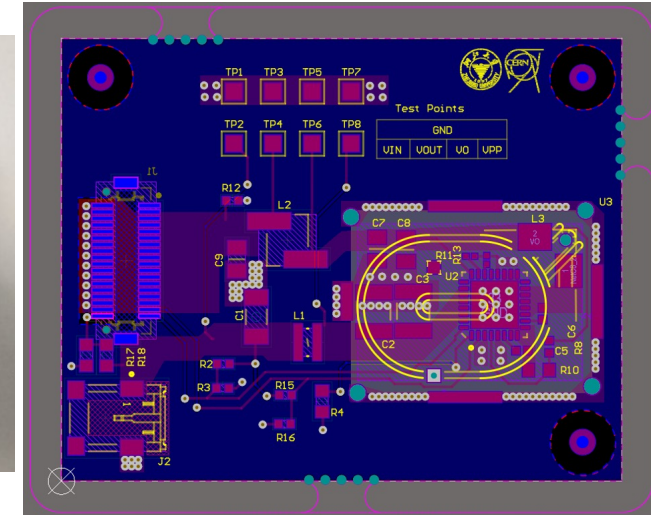
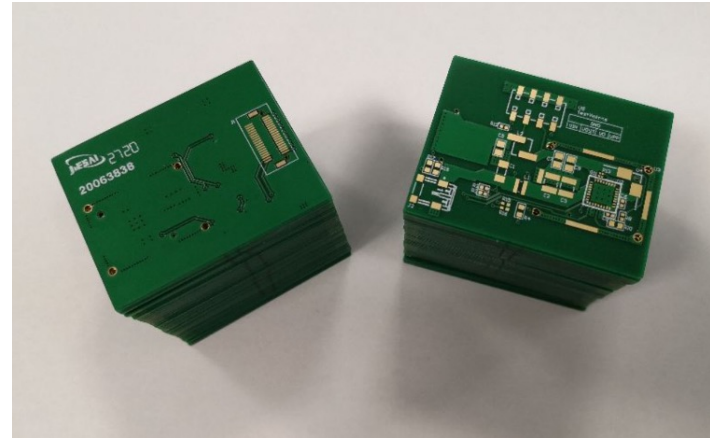


# Half-hexaboard design

ZJU's designing the half module front-end board



- DCDC PCB **design and test production of 60 boards**
- Half bottom partial hexaboard **design**
  - 8-layer layout
  - Preliminary version reviewed by HGCal



## Hexaboards Design Status

HGCAL Week Workshop  
Summer 2022

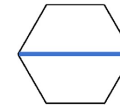
Hafiza Ayesha Ahmed (CERN/OL-PAK)

Fakhri Alam Khan (CERN/ULB)

Noman Saud (CERN/OL-PAK)

Zhen Lin (ZJU-China)

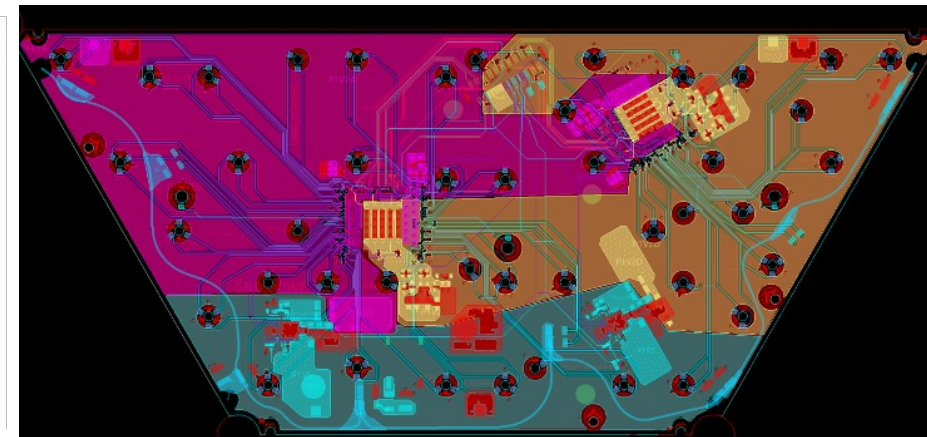
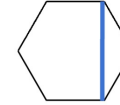
Two Halves : Top & **Bottom**



Two Semis : Left & Right



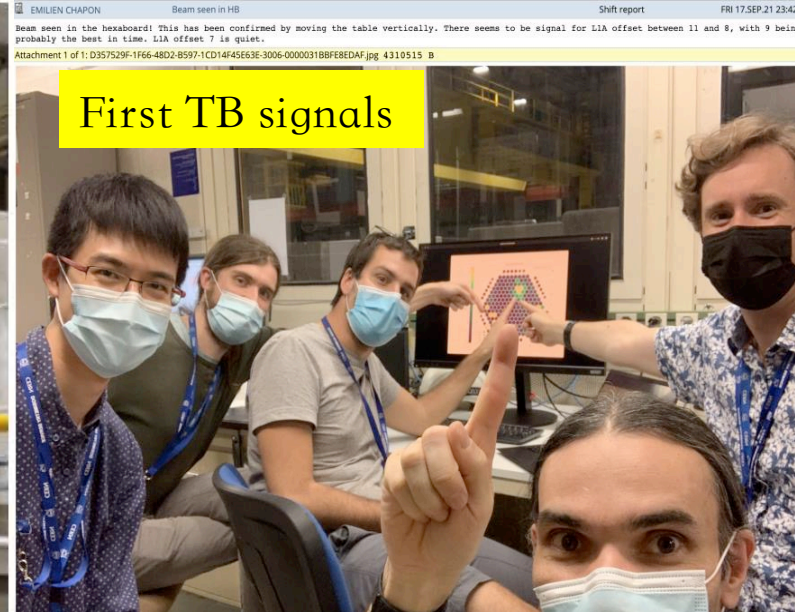
One Five and One Three



# Activities at CERN

TB for the first 8 inch modules at H8, qualification of HGCROC2 and hexaboards, etc.

TB setup at H8



Module to wirebond: [ ]  
wirebonding date: 1/1/21  
Pre-wirebonding qualification: [ ]  
Wirebonding: Back side [ ]  
Wirebonds inspected: [ ]  
Wirebonds repaired user: [ ]  
Encapsulation: Back side [ ]  
Encapsulation user: [ ]  
oven cure start: 1/1/20 12:00 AM  
oven cure stop: 1/1/20 12:00 AM  
Post-curing inspection: [ ]

Text formatting errors: [ ]  
Note: Format of all text box input should be a comma-separated list of values. ex. 1, 3, 4, ...  
Wirebonding qualification: [ ]  
Final inspection OK?: [ ]  
wirebonding notes: [ ]  
encapsulation notes: [ ]

Parts, tooling, and supplies  
search for parts  
baseplates  
sensors  
PCBs  
protomodules  
modules  
tooling  
supplies

Production steps and testing  
kapton placement steps  
sensor placement steps  
PCB placement steps  
wirebonding and encapsulating

Shipping and receiving  
shipments

Uploading to the HGCAL DB  
Upload current object  
Upload objects created on date: 1/1/21  
Upload objects

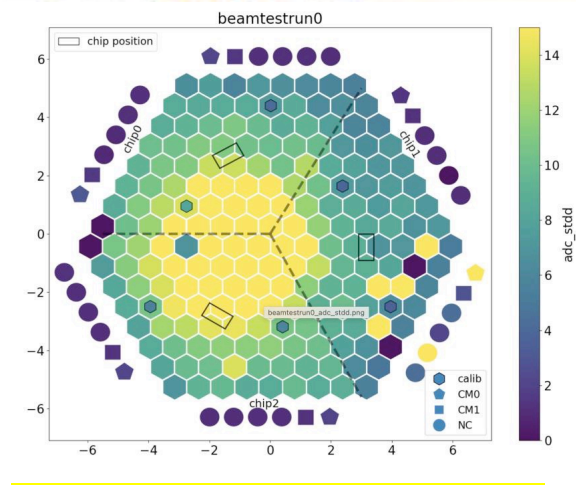
Upload status

HGCAL database

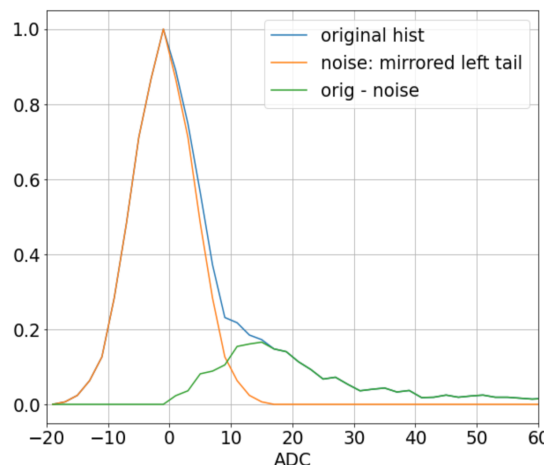
Émilien Chapon, Fabio Monti (IHEP)

HGCAL Database: an essential part of HGCAL project

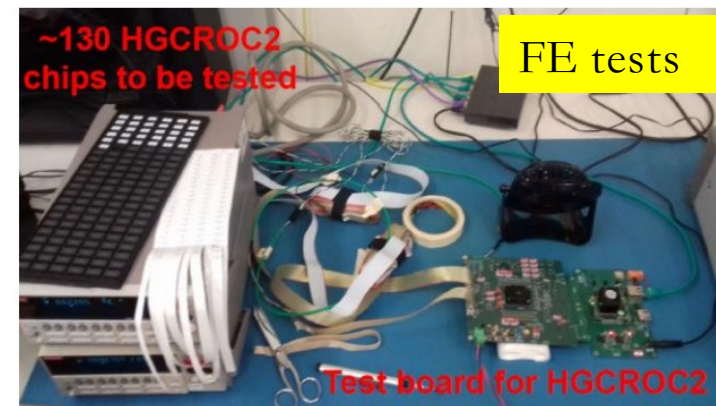
- Record data of all steps in module production
- Transmit information between local MAC and HGCAL database
- Sensors, PCBs, baseplates, tooling; production steps and testing results; shipping



Shower signals from TB



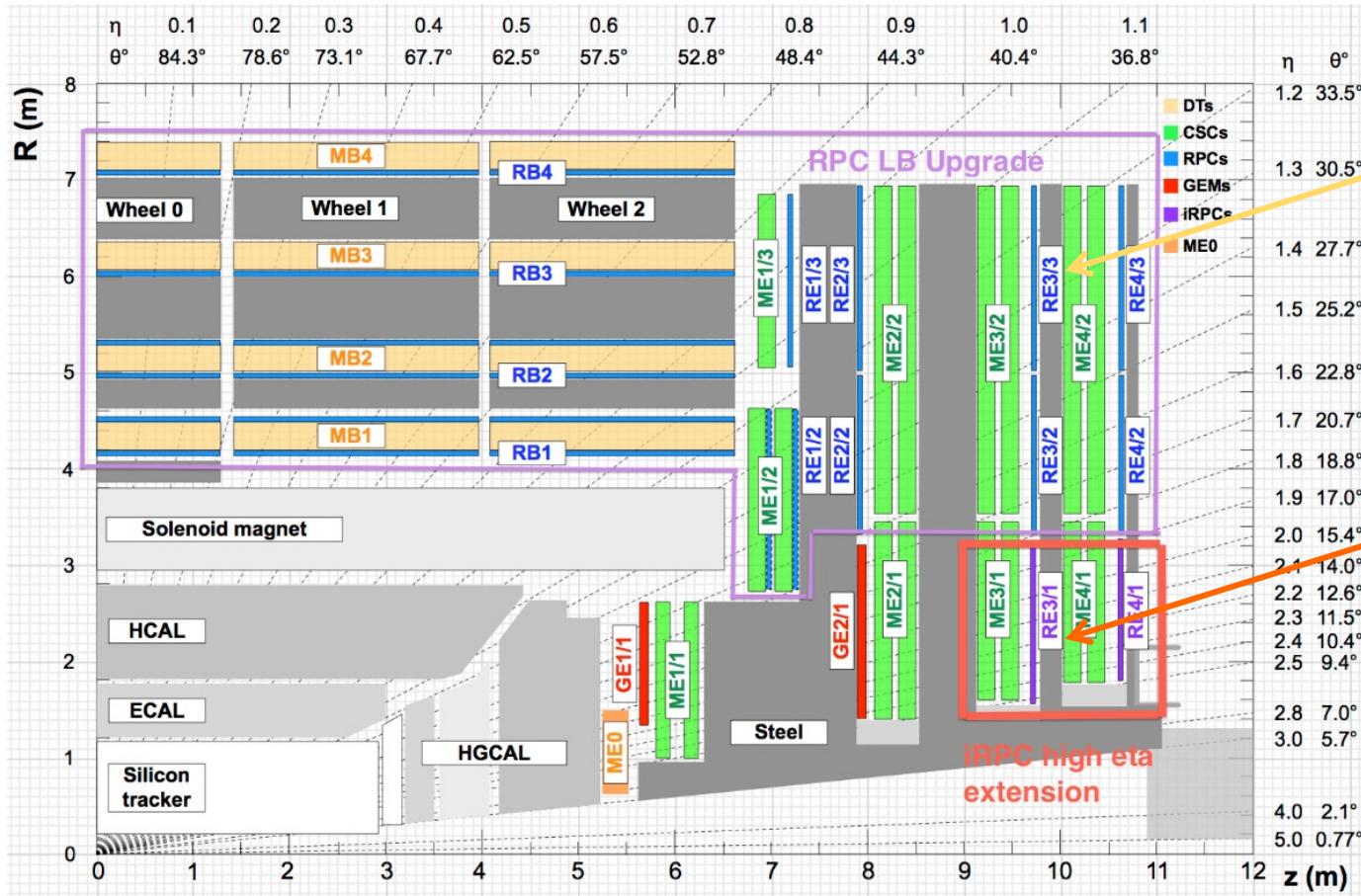
Sign of MIP signals





# The RPC BE/TRG project IHEP

iRPC/RPC backend electronics and trigger system



**New link system for existing RPC**

Upgrade of **Link System** to improve timing resolution for existing RPC ( $|\eta| < 1.9$ )

**New iRPC and FEB**

Extend the **RPC coverage** up to  $|\eta| = 2.4$  to increase redundancy in high eta region in stations 3 and 4

**Backend Electronics (BE) and Trigger (TRG) need to be designed for new RPC Link System and iRPC.**

Improved Resistive Plate Chamber, **iRPC**, designed for high particle fluxes (up to  $2\text{ k Hz} \cdot \text{cm}^{-2}$ ) will be equipped in high pseudorapidity stations (**RE3/1** and **RE4/1**)

These are double-gap RPC (gap size of 1.4mm) to reduce the amount of the avalanche charge produced -> improved RPC count rate

Challenges in electronics: **low-noise, high time resolution, able to deal with lower charge signal**

# iRPC/RPC BE/TRG task and schedule

Three major components by IHEP



## ◆ iRPC backend:

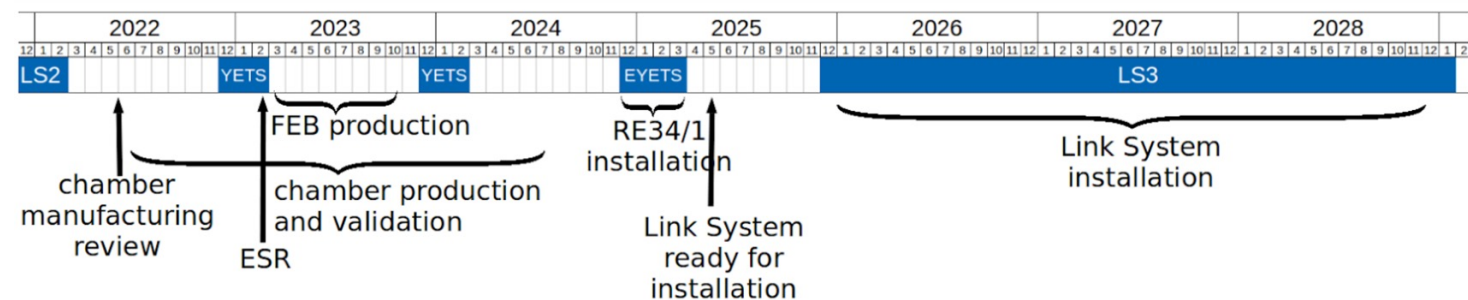
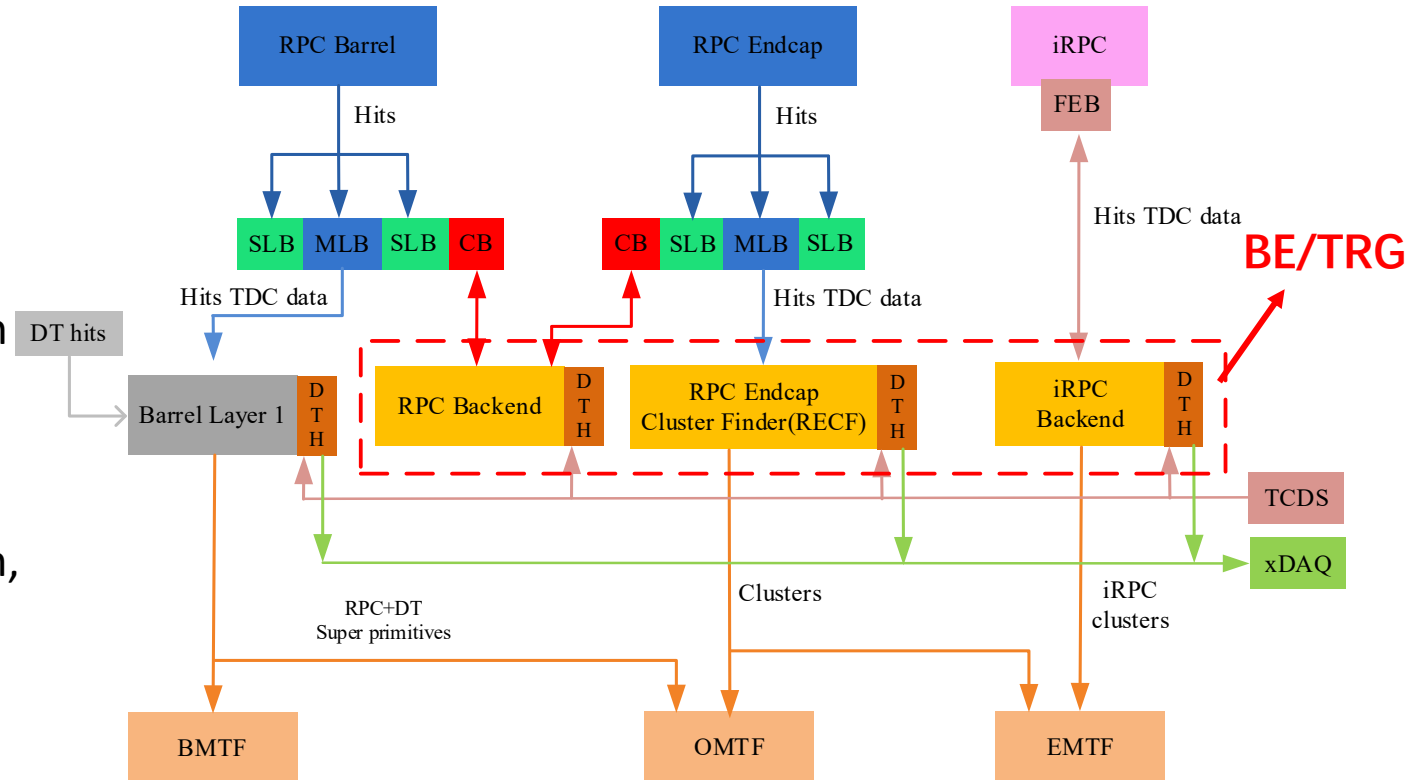
- Fast Control/TTC,
- Slow control/Monitor,
- Data readout,
- Trigger Primitive(Cluster) Generation

## ◆ RPC Endcap Cluster Finder(RECF):

- Data readout,
- Trigger Primitive(Cluster) Generation,
- TP data Fanout

## ◆ RPC backend:

- Fast Control/TTC
- Slow control,
- monitor



# iRPC $\mu$ TCA BE/TRG demonstrator system

Layout of the components

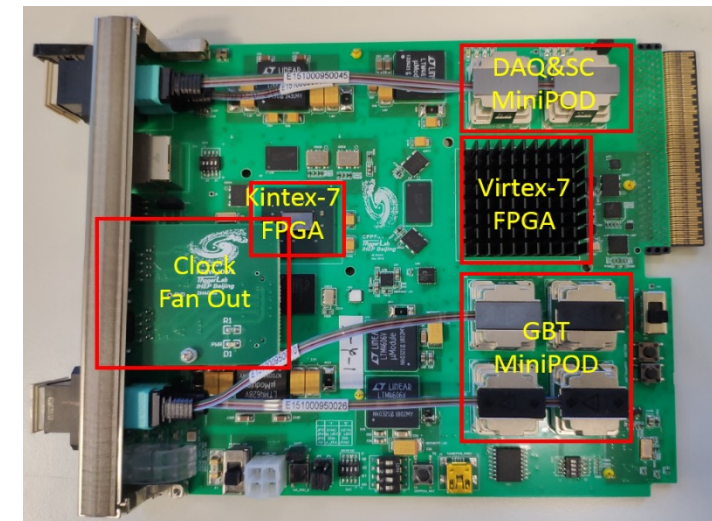
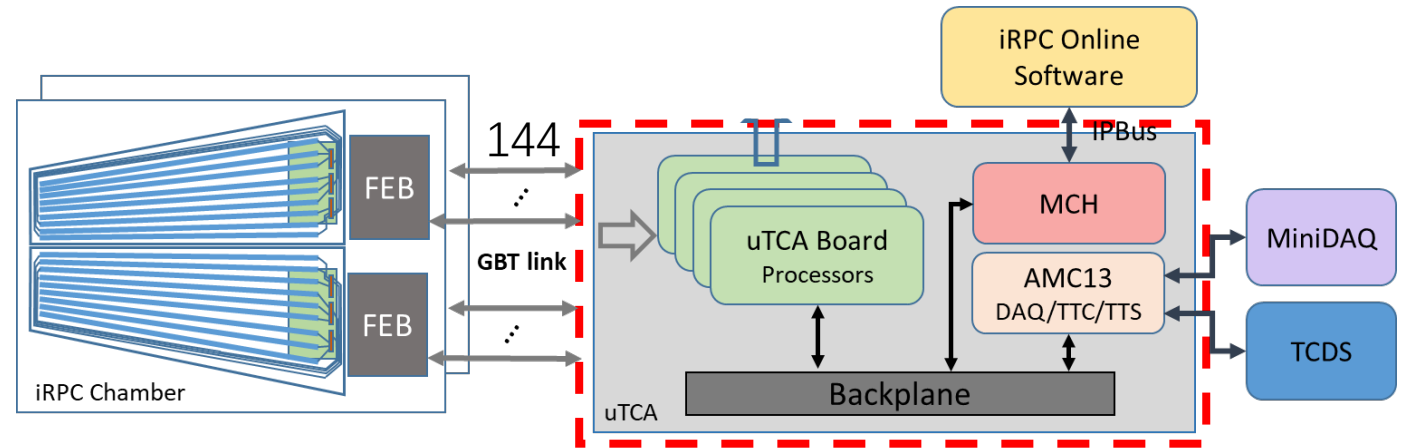
- iRPC BE/TRG demonstrator system

- **$\mu$ TCA compliant BE boards**

- core board
  - an AMC13 card
    - system clock and fast control
  - a  $\mu$ TCA Carrier Hub (MCH)
    - manage the whole system
  - a  $\mu$ TCA crate
  - a sever PC
    - slow control and DAQ

- **BE/TRG board:**

- Virtex-7 FPGA: Core FPGA ( GBT Communication with Feb + data processing)
  - Kintex-7 FPGA: Control FPGA (clock configuration , SC)

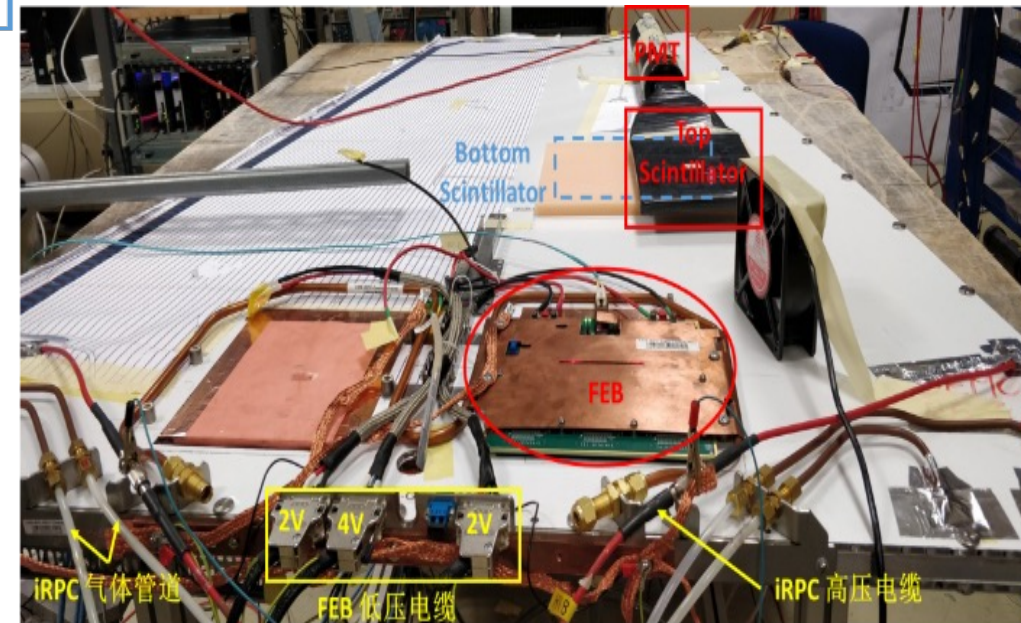
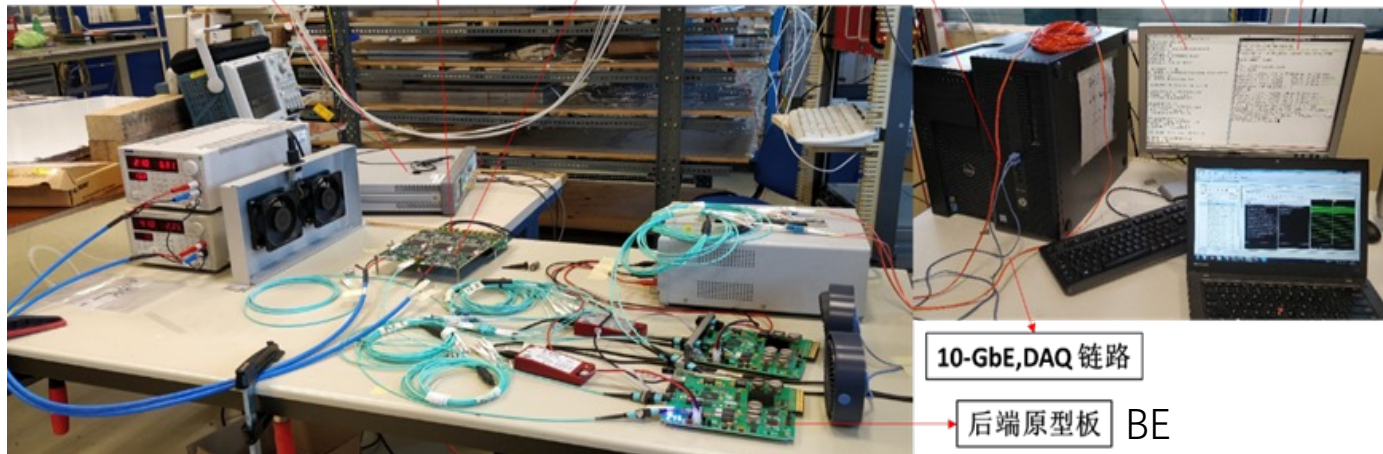
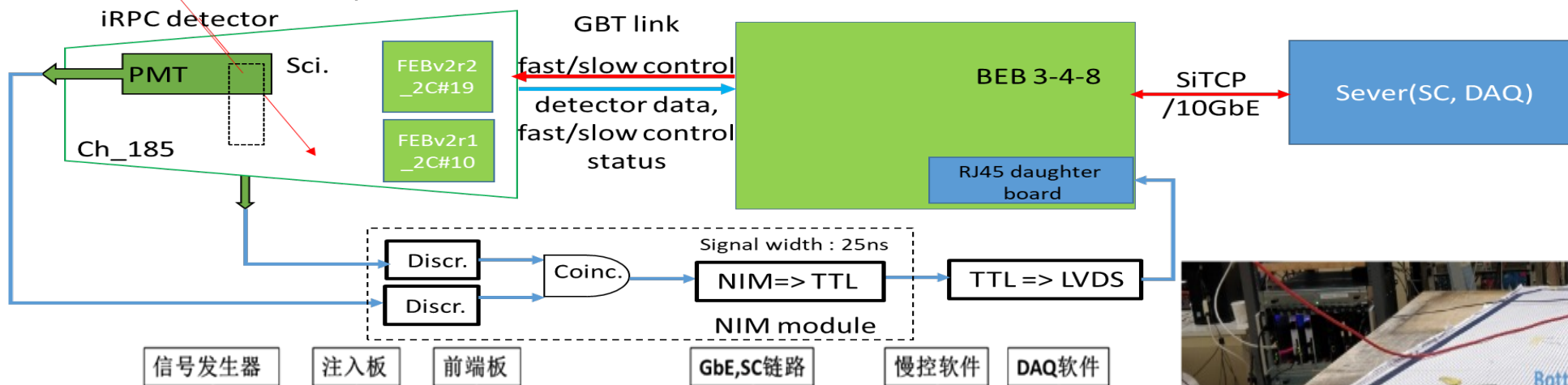


# Joint test with FEB and Chamber in 904

Testing the RPC chamber, FEB and BE all together with cosmic data

Joint test system setup at CERN in 904 from July 2021, **basic function of BE has been verified**

Second stage of Joint test started from Oct 2021 and focused on **cosmic data taking** for FEB and backend performance studies



# Joint test with FEB and Chamber in 904

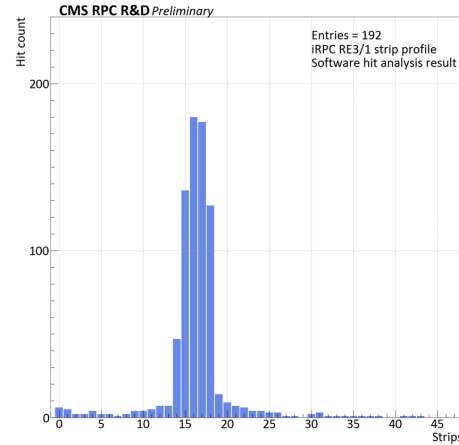
Test results with cosmic data



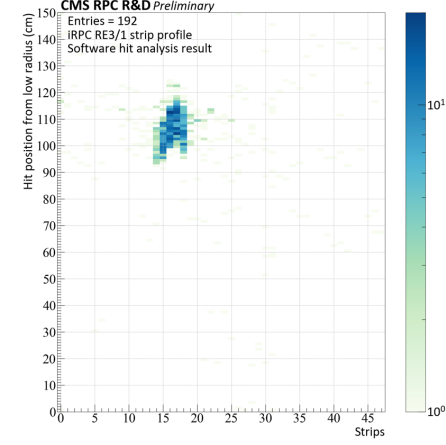
Cosmic Data taking successfully with FEB and chamber

Study on hit position, cluster position distribution and other cluster characteristics

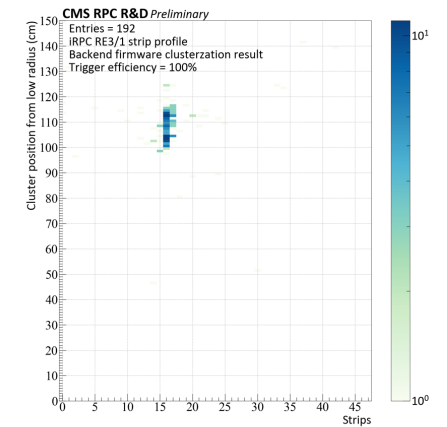
Studying on high voltage efficiency scan under different **DAQ readout windows** and proposing solution suggestion to FEB team



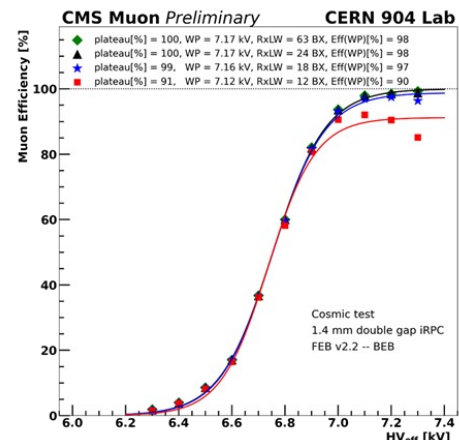
Hits distribution on strips



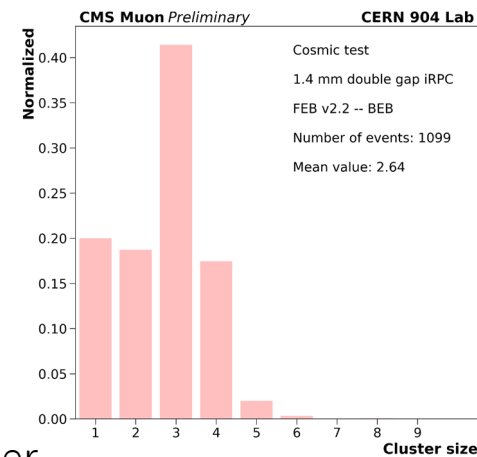
Hits position distribution on chamber



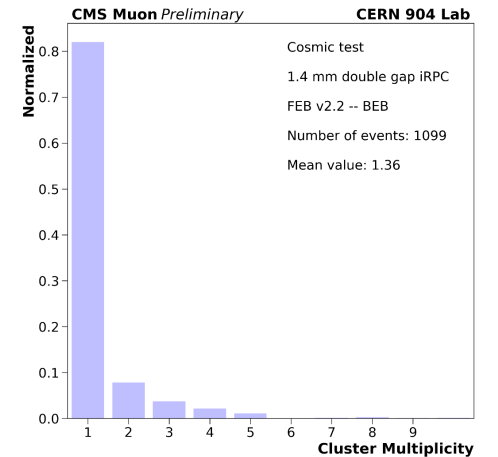
Clusterization distribution



High voltage efficiency scan under different DAQ readout window



Cluster size distribution



Cluster multiplicity

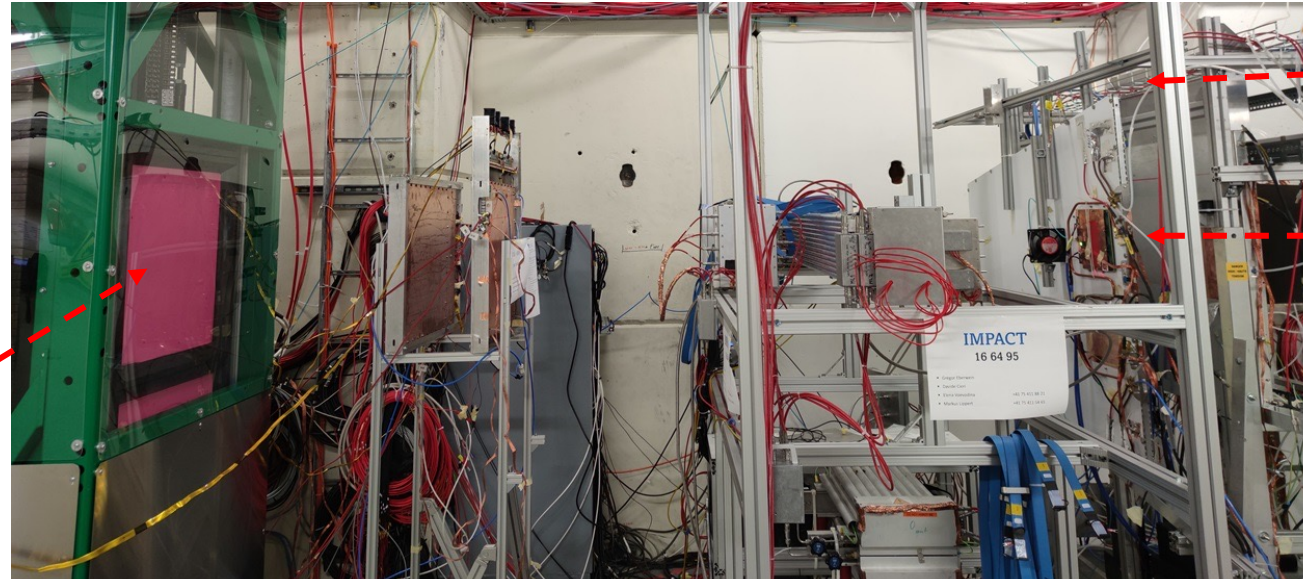
# iRPC BE/TRG beam test in GIF++

The setup

Beam test in GIF++  
conducted from 2022.10.19  
to 11.2.

$\gamma$  background source

Inside bunker

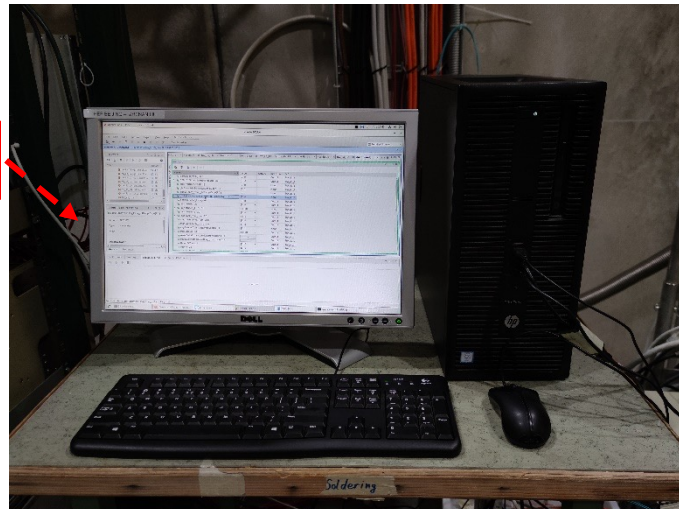


Chamber\_190

FEB v2\_2c

Outside bunker

DAQ and IPbus SC server



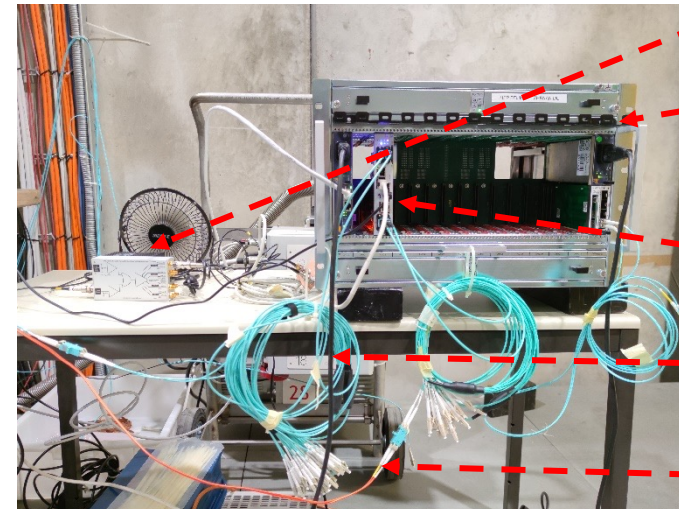
L1A trigger

mTCA crate

BEB

GBT link

10GbE DAQ

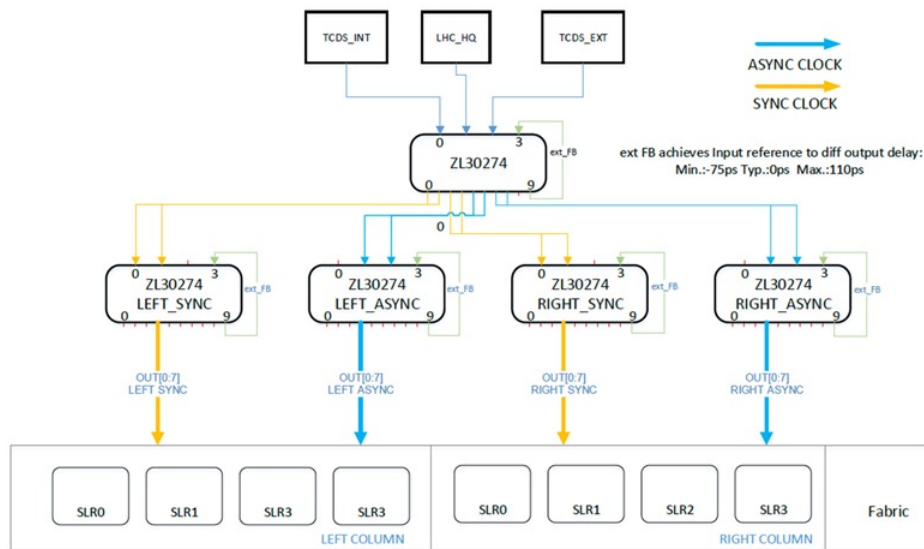


# Serenity S1 board design

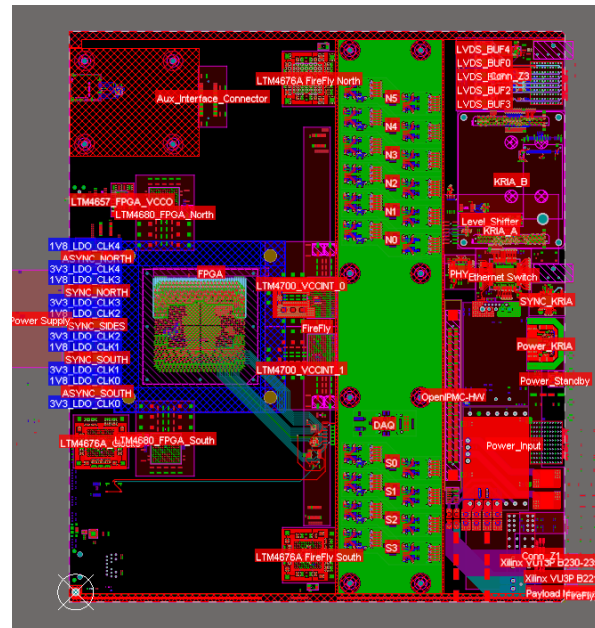
The DAQ system

Joined Serenity steering committee, design group and layout group for Serenity board design

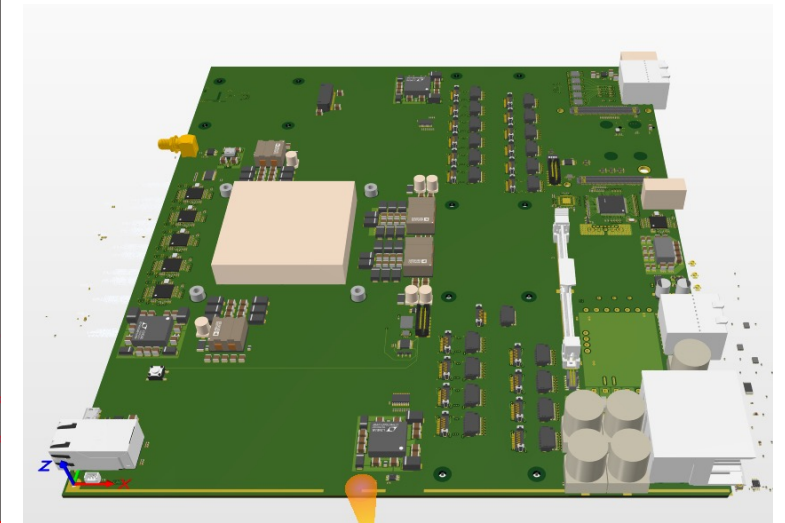
Provided **clock tree design scheme**, and joint the schematic and PCB layout design



Clock tree design scheme for Serenity S1



2D view of Serenity S1 PCB



3D view of Serenity S1 PCB

# Summary

Activities mainly from the last year

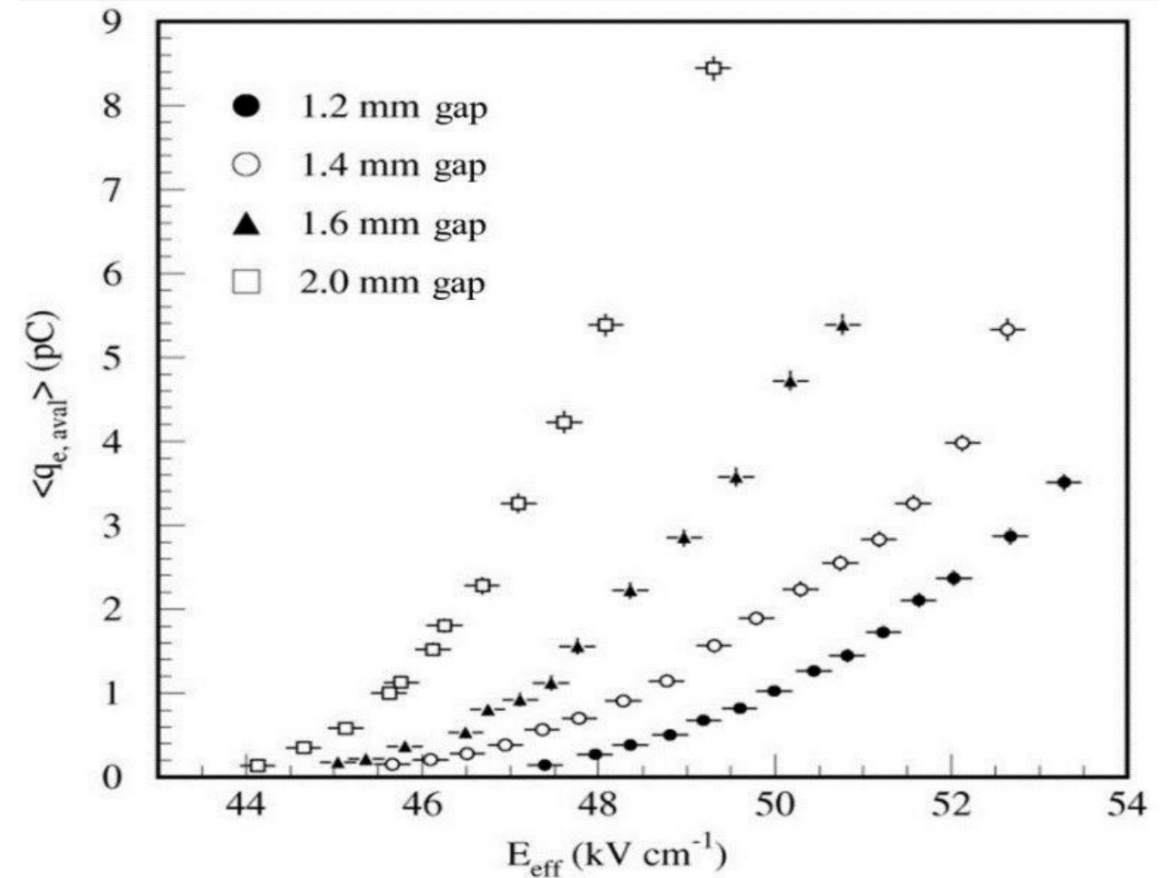


- CMS Phase-II upgrade projects are progressing smoothly, with many important contributions from CMS-China
  - **GEM** completed the GE2/1 GEB design and production, started the first batch of **mass production of GE2/1 full detector** (first in CMS!)
  - **MTD** is actively preparing the **assembly center** and test benches
  - **HGCal** produced first small **batch of 8 inch silicon modules** (first in CMS!)
  - **iRPC/RPC** BE/TRGB had **joint test with FEBs and cambers** using cosmic data taking, joined serenity board design with main contribution in the **clock tree scheme**
- Three assembly centers GEM, MTD and HGCal are going to take significant fraction of the detector assembly work
  - **PKU GEM and IHEP HGCal** got CERN certification of the assembly centers
  - **PKU MTD** got approved to build the assembly center and started the preparation



Backup slides

	RPC	iRPC
N gas gap	2	2
Gas Gap	2 mm	1.4 mm
High Pressure Laminate	2 mm	1.4 mm
Resistivity ( $\Omega\text{cm}$ )	$1 - 6 \times 10^{10}$	$0.9 - 3 \times 10^{10}$
Strip pitch	2-4 cm	0.7-1.2 cm
Electronics Threshold	150 fC	10 fC
Chamber dimension	10 degrees	20 degrees



The thinner gap thicknesses:

- more effectively retard the fast growth of the pickup charges of the ionization avalanches
- reduce aging effect
- reduce of the operational high voltage from 9.5 kV to 7.1 kV improving the robustness of the system and reducing the failure probability of the HV system

# PKU production site and activities at CERN

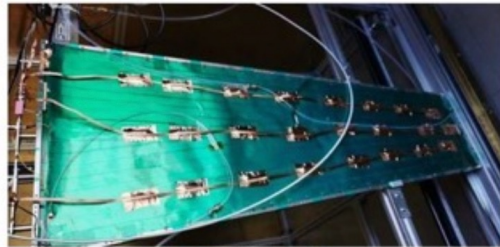
## Local and CERN

- PKU GEM assembly and QC laboratory ready, with cleanroom and hardware/software platforms
  - Mar. 2021: PKU GEM Lab. **passed the review of CMS-GEM collaboration, becomes one of the official CMS-GEM production sites**
- Summers in 2021 and 2022: PKU members participated the assembly and test of GE2/1 GEM at CERN

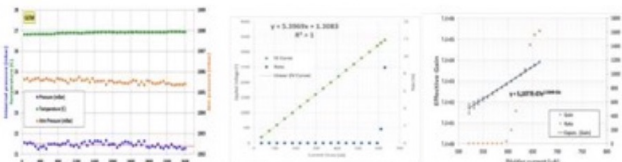
- Completed gas-tightness, HV performance and gain test etc. with **full-size GE1/1 GEM**, QC procedure setup done.



GEM X ray gain test at PKU

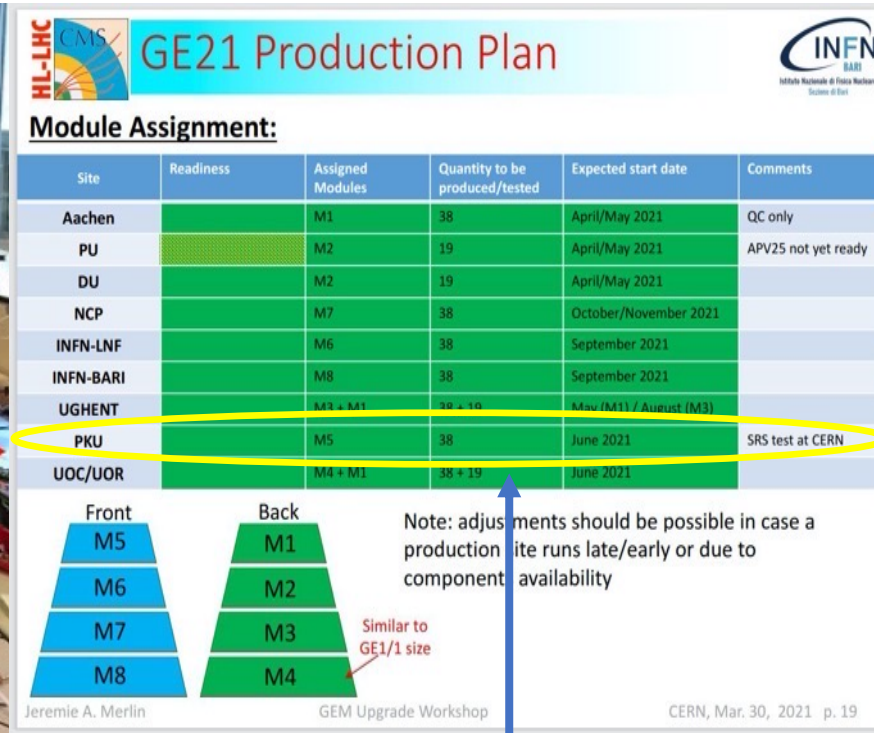


Full-size GE1/1 GEM detector



→ GEM Production site in PKU is ready

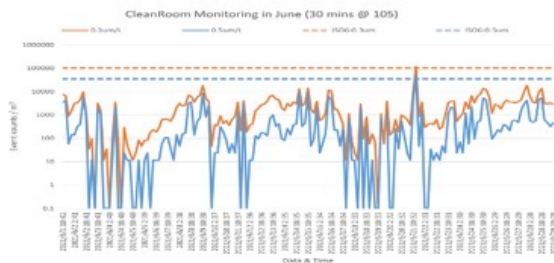
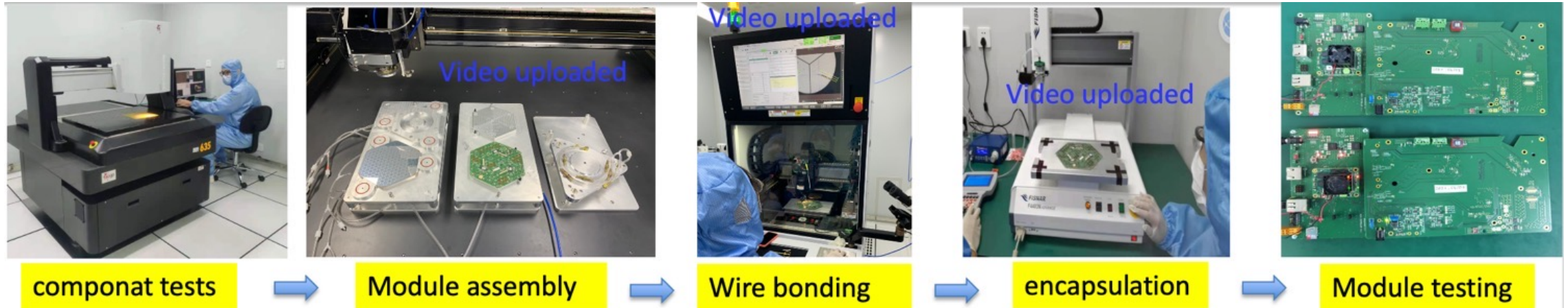
Test of Full-size GE1/1 GEM at PKU lab



Production share

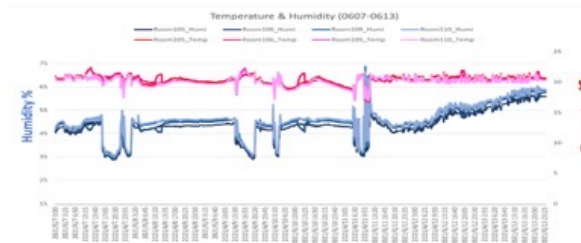
# Responsibilities of MACs

From module assembly to QA/QC as required by the MAC certification



## Cleanroom status

- Cleanness
- Temperature
- Humidity



- Clean room and major equipment are installed, operator trained
- Fixture for gantry, wire bonder, pull tester, encapsulation are fabricated
- Glue partern for assembly, encapsulation and wire bonding code are tested
- Go through full production chain for the first time on real componats (next slide)

